



APPENDIX A ELECTRICAL CHARACTERISTICS

This appendix contains electrical specification tables and reference timing diagrams for the MC68332 and the MC68LK332.

Table A-1 Maximum Ratings

Num	Rating	Symbol	Value	Unit
1	Supply Voltage ^{1, 2, 7}	V_{DD}	-0.3 to + 6.5	V
2	Input Voltage ^{1, 2, 3, 5, 7}	V_{in}	-0.3 to + 6.5	V
3	Instantaneous Maximum Current Single pin limit (applies to all pins) ^{1, 5, 6, 7}	I_D	25	mA
4	Operating Maximum Current Digital Input Disruptive Current ^{4, 5, 6, 7, 8} $V_{NEGCLAMP} \equiv -0.3 \text{ V}$ $V_{POSCLAMP} \equiv V_{DD} + 0.3$	I_{ID}	-500 to 500	μA
5	Operating Temperature Range MC68332 No Suffix MC68332 "C" Suffix MC68332 "V" Suffix MC68332 "M" Suffix	T_A	T_L to T_H 0 to 70 -40 to 85 -40 to 105 -40 to 125	$^{\circ}\text{C}$
6	Storage Temperature Range	T_{stg}	-55 to 150	$^{\circ}\text{C}$

NOTES:

1. Permanent damage can occur if maximum ratings are exceeded. Exposure to voltages or currents in excess of recommended values affects device reliability. Device modules may not operate normally while being exposed to electrical extremes.
2. Although sections of the device contain circuitry to protect against damage from high static voltages or electrical fields, take normal precautions to avoid exposure to voltages higher than maximum-rated voltages.
3. All pins except T_{STME}/T_{SC} .
4. All functional non-supply pins are internally clamped to V_{SS} . All functional pins except EXTAL, TSC, and XFC are internally clamped to V_{DD} .
5. Input must be current limited to the value specified. To determine the value of the required current-limiting resistor, calculate resistance values for positive and negative clamp voltages, then use the larger of the two values.
6. Power supply must maintain regulation within operating V_{DD} range during instantaneous and operating maximum current conditions.
7. This parameter is periodically sampled rather than 100% tested.
8. Total input current for all digital input-only and all digital input/output pins must not exceed 10 mA. Exceeding this limit can cause disruption of normal operation.



Table A-2 MC68LK332 Typical Ratings

Num	Rating	Symbol	Value	Unit
1	Supply Voltage	V_{DD}	3.3	V
2	Operating Temperature	T_A	25	°C
3	V_{DD} Supply Current RUN LPSTOP, VCO off LPSTOP, External clock, max f_{sys}	I_{DD}	45 125 1.0	mA μ A mA
4	Clock Synthesizer Operating Voltage	V_{DDSYN}	3.3	V
5	V_{DDSYN} Supply Current VCO on, maximum f_{sys} External Clock, maximum f_{sys} LPSTOP, VCO off V_{DD} powered down	I_{DDSYN}	1.0 2.0 100 50	mA mA μ A μ A
6	RAM Standby Current Normal RAM operation Standby operation	I_{SB}	3.0 10	μ A μ A
7	Power Dissipation	P_D	148.0	mW

Table A-3 MC68332 Typical Ratings — 16.78 MHz Operation

Num	Rating	Symbol	Value	Unit
1	Supply Voltage	V_{DD}	5.0	V
2	Operating Temperature	T_A	25	°C
3	V_{DD} Supply Current RUN LPSTOP, VCO off LPSTOP, External clock, maximum f_{sys}	I_{DD}	75 125 3	mA μ A mA
4	Clock Synthesizer Operating Voltage	V_{DDSYN}	5.0	V
5	V_{DDSYN} Supply Current External Clock, maximum f_{sys} 32.768 kHz Crystal Reference, VCO on, maximum f_{sys} LPSTOP, VCO off V_{DD} powered down	I_{DDSYN}	4 1 100 50	mA mA μ A μ A
6	RAM Standby Voltage	V_{SB}	3.0	V
7	RAM Standby Current Normal RAM operation Standby operation	I_{SB}	7.0 40	μ A μ A
8	Power Dissipation	P_D	455	mW



Table A-4 MC68332 Typical Ratings — 20.97 MHz Operation

Num	Rating	Symbol	Value	Unit
1	Supply Voltage	V_{DD}	5.0	V
2	Operating Temperature	T_A	25	°C
3	V_{DD} Supply Current RUN LPSTOP, VCO off LPSTOP, External clock, maximum f_{sys}	I_{DD}	113 125 3.75	mA μ A mA
4	Clock Synthesizer Operating Voltage	V_{DDSYN}	5.0	V
5	V_{DDSYN} Supply Current External Clock, maximum f_{sys} 32.768 kHz Crystal Reference, VCO on, maximum f_{sys} LPSTOP, VCO off V_{DD} powered down	I_{DDSYN}	5 1 100 50	mA mA μ A μ A
6	RAM Standby Voltage	V_{SB}	3.0	V
7	RAM Standby Current Normal RAM operation Standby operation	I_{SB}	7.0 40	μ A μ A
8	Power Dissipation	P_D	570	mW

Table A-5 MC68332 Typical Ratings — 25.17 MHz Operation

Num	Rating	Symbol	Value	Unit
1	Supply Voltage	V_{DD}	5.0	V
2	Operating Temperature	T_A	25	°C
3	V_{DD} Supply Current RUN LPSTOP, VCO off LPSTOP, External clock, maximum f_{sys}	I_{DD}	113 125 3.75	mA μ A mA
4	Clock Synthesizer Operating Voltage	V_{DDSYN}	5.0	V
5	V_{DDSYN} Supply Current External Clock, maximum f_{sys} 32.768 kHz Crystal Reference, VCO on, maximum f_{sys} LPSTOP, VCO off V_{DD} powered down	I_{DDSYN}	5 1 100 50	mA mA μ A μ A
6	RAM Standby Voltage	V_{SB}	3.0	V
7	RAM Standby Current Normal RAM operation Standby operation	I_{SB}	70 40	μ A μ A
8	Power Dissipation	P_D	570	mW



Table A-6 Thermal Characteristics

Num	Characteristic	Symbol	Value	Unit
1	Thermal Resistance	Θ_{JA}		$^{\circ}\text{C/W}$
	Plastic 132-Pin Surface Mount		38	
	Plastic 144-Pin Surface Mount		46	
	Thin Plastic 144-Pin Surface Mount		49	

The average chip-junction temperature (T_J) in C can be obtained from:

$$T_J = T_A + (P_D \times \Theta_{JA}) \quad (1)$$

where:

T_A = Ambient Temperature, $^{\circ}\text{C}$

Θ_{JA} = Package Thermal Resistance, Junction-to-Ambient, $^{\circ}\text{C/W}$

$P_D = P_{INT} + P_{I/O}$

$P_{INT} = I_{DD} \times V_{DD}$, Watts — Chip Internal Power

$P_{I/O}$ = Power Dissipation on Input and Output Pins — User Determined

For most applications $P_{I/O} < P_{INT}$ and can be neglected. An approximate relationship between P_D and T_J (if $P_{I/O}$ is neglected) is:

$$P_D = K \div (T_J + 273^{\circ}\text{C}) \quad (2)$$

Solving equations 1 and 2 for K gives:

$$K = P_D \times (T_A + 273^{\circ}\text{C}) + \Theta_{JA} \times P_D^2 \quad (3)$$

where K is a constant pertaining to the particular part. K can be determined from equation (3) by measuring P_D (at equilibrium) for a known T_A . Using this value of K, the values of P_D and T_J can be obtained by solving equations (1) and (2) iteratively for any value of T_A .

Table A-7 Low Voltage Clock Control Timing

(V_{DD} and $V_{DDSYN} = 3.0$ to 3.6 Vdc, $V_{SS} = 0$ Vdc, $T_A = T_L$ to T_H)

Num	Characteristic	Symbol	Min	Max	Unit
1	PLL Reference Frequency Range	f_{ref}	20	50	kHz
2	System Frequency ¹	f_{sys}	$4(f_{ref})_{dc}$	16.78	MHz
	On-Chip PLL System Frequency External Clock Operation			16.78	
3	PLL Lock Time ^{2, 3, 4, 5}	t_{pll}	—	20	ms
4	VCO Frequency ⁶	f_{VCO}	—	$2 (f_{sys} \text{ max})$	MHz
5	CLKOUT Jitter ^{2, 3, 4, 7}	J_{clk}	-1.0 -0.5	1.0	%
	Short term (5 μs interval)			0.5	
	Long term (500 μs interval)				

NOTES:

1. Refer to notes in [Table A-10](#).



Table A-8 16.78 MHz Clock Control Timing

(V_{DD} and $V_{DDSYN} = 5.0 \text{ Vdc} \pm 10\%$, $V_{SS} = 0 \text{ Vdc}$, $T_A = T_L$ to T_H , 32.768 kHz reference)

Num	Characteristic	Symbol	Min	Max	Unit
1	PLL Reference Frequency Range	f_{ref}	25	50	kHz
2	System Frequency ¹ On-Chip PLL System Frequency External Clock Operation	f_{sys}	$4(f_{ref})_{dc}$	16.78 16.78	MHz
3	PLL Lock Time ^{2, 3, 4, 5}	t_{lpl}	—	20	ms
4	VCO Frequency ⁶	f_{VCO}	—	$2 (f_{sys} \text{ max})$	MHz
5	Limp Mode Clock Frequency SYNCR X bit = 0 SYNCR X bit = 1	f_{limp}	— —	$f_{sys} \text{ max} / 2$ $f_{sys} \text{ max}$	MHz
6	CLKOUT Jitter ^{2, 3, 4, 7} Short term (5 μs interval) Long term (500 μs interval)	J_{clk}	−0.5 −0.05	0.5 0.05	%

NOTES:

1. Refer to notes in [Table A-10](#).

Table A-9 20.97 MHz Clock Control Timing

(V_{DD} and $V_{DDSYN} = 5.0 \text{ Vdc} \pm 5\%$, $V_{SS} = 0 \text{ Vdc}$, $T_A = T_L$ to T_H , 32.768 kHz reference)

Num	Characteristic	Symbol	Min	Max	Unit
1	PLL Reference Frequency Range	f_{ref}	25	50	kHz
2	System Frequency ¹ On-Chip PLL System Frequency External Clock Operation	f_{sys}	$4(f_{ref})_{dc}$	20.97 20.97	MHz
3	PLL Lock Time ^{2, 3, 4, 5}	t_{lpl}	—	20	ms
4	VCO Frequency ⁶	f_{VCO}	—	$2 (f_{sys} \text{ max})$	MHz
5	Limp Mode Clock Frequency SYNCR X bit = 0 SYNCR X bit = 1	f_{limp}	— —	$f_{sys} \text{ max} / 2$ $f_{sys} \text{ max}$	MHz
6	CLKOUT Jitter ^{2, 3, 4, 7} Short term (5 μs interval) Long term (500 μs interval)	J_{clk}	−0.5 −0.05	0.5 0.05	%

NOTES:

1. Refer to notes in [Table A-10](#).



Table A-10 25.17 MHz Clock Control Timing

(V_{DD} and $V_{DDSYN} = 5.0 \text{ Vdc} \pm 5\%$, $V_{SS} = 0 \text{ Vdc}$, $T_A = T_L$ to T_H , 32.768 kHz reference)

Num	Characteristic	Symbol	Min	Max	Unit
1	PLL Reference Frequency Range	f_{ref}	25	50	kHz
2	System Frequency ¹ On-Chip PLL System Frequency External Clock Operation	f_{sys}	$4(f_{ref})_{dc}$	25.17 25.17	MHz
3	PLL Lock Time ^{2,3,4,5}	t_{lpl}	—	20	ms
4	VCO Frequency ⁶	f_{VCO}	—	$2 (f_{sys} \text{ max})$	MHz
5	Limp Mode Clock Frequency SYNCR X bit = 0 SYNCR X bit = 1	f_{limp}	— —	$f_{sys} \text{ max} / 2$ $f_{sys} \text{ max}$	MHz
6	CLKOUT Jitter ^{2, 3, 4, 7} Short term (5 μs interval) Long term (500 μs interval)	J_{clk}	-0.5 -0.05	1.0 0.5	%

NOTES:

1. All internal registers retain data at 0 Hz.
2. This parameter is periodically sampled rather than 100% tested.
3. Assumes that a low-leakage external filter network is used to condition clock synthesizer input voltage. Total external resistance from the XFC pin due to external leakage must be greater than 15 M Ω to guarantee this specification. Filter network geometry can vary depending upon operating environment.
4. Proper layout procedures must be followed to achieve specifications.
5. Assumes that stable V_{DDSYN} is applied, and that the crystal oscillator is stable. Lock time is measured from the time V_{DD} and V_{DDSYN} are valid until **RESET** is released. This specification also applies to the period required for PLL lock after changing the W and Y frequency control bits in the synthesizer control register (SYNCR) while the PLL is running, and to the period required for the clock to lock after LPSTOP.
6. Internal VCO frequency (f_{VCO}) is determined by SYNCR W and Y bit values. The SYNCR X bit controls a divide-by-two circuit that is not in the synthesizer feedback loop. When X = 0, the divider is enabled, and $f_{sys} = f_{VCO} \div 4$. When X = 1, the divider is disabled, and $f_{sys} = f_{VCO} \div 2$. X must equal one when operating at maximum specified f_{sys} .
7. Jitter is the average deviation from the programmed frequency measured over the specified interval at maximum f_{sys} . Measurements are made with the device powered by filtered supplies and clocked by a stable external clock signal. Noise injected into the PLL circuitry via V_{DDSYN} and V_{SS} and variation in crystal oscillator frequency increase the J_{clk} percentage for a given interval. When jitter is a critical constraint on control system operation, this parameter should be measured during functional testing of the final system.



Table A-11 Low Voltage 16.78 MHz DC Characteristics

(V_{DD} and $V_{DDSYN} = 3.0$ to 3.6 Vdc, $V_{SS} = 0$ Vdc, $T_A = T_L$ to T_H)

Num	Characteristic	Symbol	Min	Max	Unit
1	Input High Voltage	V_{IH}	$0.7 (V_{DD})$	$V_{DD} + 0.3$	V
2	Input Low Voltage	V_{IL}	$V_{SS} - 0.3$	$0.2 (V_{DD})$	V
3	Input Hysteresis ¹	V_{HYS}	0.5	—	V
4	Input Leakage Current ² $V_{in} = V_{DD}$ or V_{SS} Input-only pins	I_{in}	-2.5	2.5	μ A
5	High Impedance (Off-State) Leakage Current ² $V_{in} = V_{DD}$ or V_{SS} All input/output and output pins	I_{OZ}	-2.5	2.5	μ A
6	CMOS Output High Voltage ^{2, 3} $I_{OH} = -10.0 \mu$ A Group 1, 2, 4 input/output and output pins	V_{OH}	$V_{DD} - 0.2$	—	V
7	CMOS Output Low Voltage ² $I_{OL} = 10.0 \mu$ A Group 1, 2, 4 input/output and output pins	V_{OL}	—	0.2	V
8	TTL Compatible Output High Voltage ^{2, 3} $I_{OH} = -0.4$ mA Group 1, 2, 4 input/output and output pins	V_{OH}	$V_{DD} - 0.5$	—	V
9	TTL Compatible Output Low Voltage ² $I_{OL} = 0.8$ mA Group 1 I/O pins, CLKOUT, FREEZE/QUOT, IPIPE/DSO $I_{OL} = 2.6$ mA Group 2 and Group 4 I/O pins, CSBOOT, BG/CS1 $I_{OL} = 6.0$ mA Group 3	V_{OL}	— — —	0.4 0.4 0.4	V
10	Three State Control Input High Voltage	V_{IHTSC}	$2.4 (V_{DD})$	9.1	V
11	Data Bus Mode Select Pull-up Current ⁴ $V_{in} = V_{IL}$ $V_{in} = V_{IH}$	I_{MSP}	— -8	-95 —	μ A
12	V_{DD} Supply Current ⁵ Run LPSTOP, external clock input frequency = max f_{sys} Run, emulation mode LPSTOP, crystal reference, VCO off (STSIM = 0)	I_{DD}	— — — —	56 2 59 350	mA mA mA μ A
13	Clock Synthesizer Operating Voltage	V_{DDSYN}	3.0	3.6	V
14	V_{DDSYN} Supply Current External clock, maximum f_{sys} Crystal reference, VCO on, maximum f_{sys} LPSTOP, crystal reference, VCO off, (STSIM = 0) V_{DD} powered down	I_{DDSYN}	— — — —	3 1 150 100	mA mA μ A μ A
15	RAM Standby Voltage Specified V_{DD} applied $V_{DD} = V_{SS}$	V_{SB}	0.0 2.7	V_{DD} 3.6	V
16	RAM Standby Current ^{6, 7} Normal RAM operation $V_{DD} > V_{SB} - 0.5$ V Transient condition $V_{SB} - 0.5$ V $\geq V_{DD} \geq V_{SS} + 0.5$ V Standby operation $V_{DD} < V_{SS} + 0.5$ V	I_{SB}	— — —	10 3 50	μ A mA μ A
17	Power Dissipation ⁸	P_D	—	212	mW

Table A-11 Low Voltage 16.78 MHz DC Characteristics (Continued)(V_{DD} and V_{DDSYN} = 3.0 to 3.6 Vdc, V_{SS} = 0 Vdc, T_A = T_L to T_H)

Num	Characteristic	Symbol	Min	Max	Unit
18	Input Capacitance ^{2, 9} All input-only pins All input/output pins	C _{in}	— —	10 20	pF
19	Load Capacitance ² Group 1 I/O Pins, CLKOUT, FREEZE/QUOT, IPIPE/DSO Group 2 I/O Pins and CSBOOT, BG/CS1 Group 3 I/O Pins Group 4 I/O Pins	C _L	— — — —	90 100 100 100	pF

NOTES:

- Applies to:
QSM pins
IRQ[7:1], RESET, EXTAL, TSC, RMC, BKPT/DSCLK, IFETCH/DSI
- Input-Only Pins: TSC, BKPT/DSCLK, RXD
Output-Only Pins: CSBOOT, BG/CS1, CLKOUT, FREEZE/QUOT, IPIPE/DSO
Input/Output Pins:
Group 1: DATA[15:0], IFETCH/DSI
Group 2: ADDR[23:19]/CS[10:6], FC[2:0]/CS[5:3], DSACK[1:0], AVEC, RMC, DS, AS, SIZ[1:0]
IRQ[7:1], MODCLK, ADDR[18:0], R/W, BERR, BR/CS0, BGACK/CS2, PCS[3:1], PCS0/SS, TXD
Group 3: HALT, RESET
Group 4: MISO, MOSI, SCK
- Does not apply to HALT and RESET because they are open drain pins.
Does not apply to Port QS[7:0] (TXD, PCS[3:1], PCS0/SS, SCK, MOSI, MISO) in wired-OR mode.
- Current measured at maximum system clock frequency.
- Total operating current is the sum of the appropriate V_{DD} supply and V_{DDSYN} supply current.
- When V_{SB} is more than 0.3V greater than V_{DD}, current flows between the V_{STBY} and V_{DD} pins, which causes standby current to increase toward the maximum condition specification. System noise on the V_{DD} and V_{STBY} pin can contribute to this condition.
- The SRAM module will not switch into standby mode as long as V_{SB} does not exceed V_{DD} by more than 0.5 volts. The SRAM array cannot be accessed while the module is in standby mode.
- Power dissipation measured with external clock at maximum specified system clock frequency, all modules active. Power dissipation can be calculated using the expression:
 $P_D = 3.6V (I_{DDSYN} + I_{DD})$
- I_{DD} includes supply currents for all device modules powered by V_{DD} pins
- Input capacitance is periodically sampled rather than 100% tested.



Table A-12 16.78 MHz DC Characteristics

(V_{DD} and $V_{DDSYN} = 5.0 \text{ Vdc} \pm 10\%$, $V_{SS} = 0 \text{ Vdc}$, $T_A = T_L$ to T_H)

Num	Characteristic	Symbol	Min	Max	Unit
1	Input High Voltage	V_{IH}	0.7 (V_{DD})	$V_{DD} + 0.3$	V
2	Input Low Voltage	V_{IL}	$V_{SS} - 0.3$	0.2 (V_{DD})	V
3	Input Hysteresis ¹	V_{HYS}	0.5	—	V
4	Input Leakage Current ² $V_{in} = V_{DD}$ or V_{SS} All input-only pins	I_{IN}	-2.5	2.5	μA
5	High Impedance (Off-State) Leakage Current ² $V_{in} = V_{DD}$ or V_{SS} All input/output and output pins	I_{OZ}	-2.5	2.5	μA
6	CMOS Output High Voltage ^{2, 3} $I_{OH} = -10.0 \mu\text{A}$ Group 1, 2, 4 input/output and all output pins	V_{OH}	$V_{DD} - 0.2$	—	V
7	CMOS Output Low Voltage ² $I_{OL} = 10.0 \mu\text{A}$ Group 1, 2, 4 input/output and all output pins	V_{OL}	—	0.2	V
8	Output High Voltage ^{2, 3} $I_{OH} = -0.8 \text{ mA}$ Group 1, 2, 4 input/output and all output pins	V_{OH}	$V_{DD} - 0.8$	—	V
9	Output Low Voltage ² $I_{OL} = 1.6 \text{ mA}$ Group1 I/O Pins, CLKOUT, FREEZE/QUOT, IPIPE $I_{OL} = 5.3 \text{ mA}$ Group 2 and Group 4 I/O Pins, $\overline{BG}/\overline{CS}$ $I_{OL} = 12 \text{ mA}$ Group 3	V_{OL}	— — —	0.4 0.4 0.4	V
10	Three State Control Input High Voltage	V_{IIHTSC}	1.6 (V_{DD})	9.1	V
11	Data Bus Mode Select Pull-up Current ⁴ $V_{in} = V_{IL}$ DATA[15:0] $V_{in} = V_{IH}$ DATA[15:0]	I_{MSP}	— -15	-120 —	μA
12	V_{DD} Supply Current ⁵ Run ⁶ LPSTOP, crystal, VCO Off (STSIM = 0) LPSTOP, external clock input frequency = maximum f_{sys}	I_{DD}	— — —	124 350 5	mA μA mA
13	Clock Synthesizer Operating Voltage	V_{DDSYN}	4.5	5.5	V
14	V_{DDSYN} Supply Current ⁵ VCO on, 32.786 kHz crystal reference, maximum f_{sys} External Clock, maximum f_{sys} LPSTOP, 32.768 kHz crystal reference, VCO off (STSIM = 0) 32.768 kHz crystal, V_{DD} powered down	I_{DDSYN}	— — — —	1 5 150 100	mA mA μA μA
15	RAM Standby Voltage Specified V_{DD} applied $V_{DD} = V_{SS}$	V_{SB}	0.0 3.0	5.5 5.5	V
16	RAM Standby Current Normal RAM operation $V_{DD} > V_{SB} - 0.5\text{V}$ Transient condition $V_{SB} - 0.5\text{V} \leq V_{DD} \leq V_{SS} + 0.5\text{V}$ Standby operation $V_{DD} < V_{SS} + 0.5\text{V}$	I_{SB}	— — —	10 3 60	μA mA μA
17	Power Dissipation ⁷	P_D	—	690	mW
18	Input Capacitance ^{2, 8} All input-only pins All input/output pins	C_{IN}	— —	10 20	pF

Table A-12 16.78 MHz DC Characteristics (Continued)(V_{DD} and V_{DDSYN} = 5.0 Vdc ±10%, V_{SS} = 0 Vdc, T_A = T_L to T_H)

Num	Characteristic	Symbol	Min	Max	Unit
19	Load Capacitance ²	C _L			pF
	Group 1 I/O Pins, CLKOUT, FREEZE/QUOT, $\overline{\text{IPIPE}}$		—	90	
	Group 2 I/O Pins and $\overline{\text{CSBOOT}}$, BG/ $\overline{\text{CS}}$		—	100	
	Group 3 I/O Pins		—	130	
	Group 4 I/O Pins		—	200	

NOTES:

1. Refer to notes in [Table A-14](#).

Table A-13 20.97 MHz DC Characteristics(V_{DD} and V_{DDSYN} = 5.0 Vdc ± 5%, V_{SS} = 0 Vdc, T_A = T_L to T_H)

Num	Characteristic	Symbol	Min	Max	Unit
1	Input High Voltage	V _{IH}	0.7 (V _{DD})	V _{DD} + 0.3	V
2	Input Low Voltage	V _{IL}	V _{SS} - 0.3	0.2 (V _{DD})	V
3	Input Hysteresis ¹	V _{HYS}	0.5	—	V
4	Input Leakage Current ² V _{in} = V _{DD} or V _{SS} All input-only pins	I _{IN}	-2.5	2.5	μA
5	High Impedance (Off-State) Leakage Current ² V _{in} = V _{DD} or V _{SS} All input/output and output pins	I _{OZ}	-2.5	2.5	μA
6	CMOS Output High Voltage ^{2, 3} I _{OH} = -10.0 μA Group 1, 2, 4 input/output and all output pins	V _{OH}	V _{DD} - 0.2	—	V
7	CMOS Output Low Voltage ² I _{OL} = 10.0 μA Group 1, 2, 4 input/output and all output pins	V _{OL}	—	0.2	V
8	Output High Voltage ^{2, 3} I _{OH} = -0.8 mA Group 1, 2, 4 input/output and all output pins	V _{OH}	V _{DD} - 0.8	—	V
9	Output Low Voltage ² I _{OL} = 1.6 mA Group 1 I/O Pins, CLKOUT, FREEZE/QUOT, $\overline{\text{IPIPE}}$ I _{OL} = 5.3 mA Group 2 and Group 4 I/O Pins, BG/ $\overline{\text{CS}}$ I _{OL} = 12 mA Group 3	V _{OL}	— — —	0.4 0.4 0.4	V
10	Three State Control Input High Voltage	V _{IHTSC}	1.6 (V _{DD})	9.1	V
11	Data Bus Mode Select Pull-up Current ⁴ V _{in} = V _{IL} DATA[15:0] V _{in} = V _{IH} DATA[15:0]	I _{MSP}	— -15	-120 —	μA
12	V _{DD} Supply Current ⁵ Run ⁶ LPSTOP, crystal, VCO Off (STSIM = 0) LPSTOP, external clock input frequency = maximum f _{sys}	I _{DD}	— — —	140 350 5	mA μA mA
13	Clock Synthesizer Operating Voltage	V _{DDSYN}	4.75	5.25	V
14	V _{DDSYN} Supply Current ⁵ VCO on, 32.786 kHz crystal reference, maximum f _{sys} External Clock, maximum f _{sys} LPSTOP, 32.768 kHz crystal reference, VCO off (STSIM = 0) 32.768 kHz crystal, V _{DD} powered down	I _{DDSYN}	— — — —	2 6 150 100	mA mA μA μA
15	RAM Standby Voltage Specified V _{DD} applied V _{DD} = V _{SS}	V _{SB}	0.0 3.0	5.25 5.25	V



Table A-13 20.97 MHz DC Characteristics (Continued)(V_{DD} and V_{DDSYN} = 5.0 Vdc ± 5%, V_{SS} = 0 Vdc, T_A = T_L to T_H)

Num	Characteristic	Symbol	Min	Max	Unit
16	RAM Standby Current	I _{SB}	—	10	μA
	Normal RAM operation				
	Transient condition				
	Standby operation				
17	Power Dissipation ⁷	P _D	—	766	mW
18	Input Capacitance ^{2, 8}	C _{IN}	—	10	pF
	All input-only pins				
	All input/output pins				
19	Load Capacitance ²	C _L	—	90	pF
	Group 1 I/O Pins, CLKOUT, FREEZE/QUOT, $\overline{\text{IPIPE}}$				
	Group 2 I/O Pins and CSBOOT, BG/CS				
	Group 3 I/O Pins				
	Group 4 I/O Pins				

NOTES:

1. Refer to notes in
- [Table A-14](#)
- .

Table A-14 25.17 MHz DC Characteristics(V_{DD} and V_{DDSYN} = 5.0 Vdc ± 5%, V_{SS} = 0 Vdc, T_A = T_L to T_H)

Num	Characteristic	Symbol	Min	Max	Unit
1	Input High Voltage	V _{IH}	0.7 (V _{DD})	V _{DD} + 0.3	V
2	Input Low Voltage	V _{IL}	V _{SS} - 0.3	0.2 (V _{DD})	V
3	Input Hysteresis ¹	V _{HYS}	0.5	—	V
4	Input Leakage Current ² V _{in} = V _{DD} or V _{SS} All input-only pins	I _{IN}	-2.5	2.5	μA
5	High Impedance (Off-State) Leakage Current ² V _{in} = V _{DD} or V _{SS} All input/output and output pins	I _{OZ}	-2.5	2.5	μA
6	CMOS Output High Voltage ^{2, 3} I _{OH} = -10.0 μA Group 1, 2, 4 input/output and all output pins	V _{OH}	V _{DD} - 0.2	—	V
7	CMOS Output Low Voltage ² I _{OL} = 10.0 μA Group 1, 2, 4 input/output and all output pins	V _{OL}	—	0.2	V
8	Output High Voltage ^{2, 3} I _{OH} = -0.8 mA Group 1, 2, 4 input/output and all output pins	V _{OH}	V _{DD} - 0.8	—	V
9	Output Low Voltage ² I _{OL} = 1.6 mA Group 1 I/O Pins, CLKOUT, FREEZE/QUOT, $\overline{\text{IPIPE}}$ I _{OL} = 5.3 mA Group 2 and Group 4 I/O Pins, BG/CS I _{OL} = 12 mA Group 3	V _{OL}	— — —	0.4 0.4 0.4	V
10	Three State Control Input High Voltage	V _{IIHTSC}	1.6 (V _{DD})	9.1	V
11	Data Bus Mode Select Pull-up Current ⁴ V _{in} = V _{IL} DATA[15:0] V _{in} = V _{IH} DATA[15:0]	I _{MSP}	— -15	-120 —	μA
12	V _{DD} Supply Current ⁵ Run ⁶ LPSTOP, crystal, VCO Off (STSIM = 0) LPSTOP, external clock input frequency = maximum f _{sys}	I _{DD}	— — —	140 350 5	mA μA mA
13	Clock Synthesizer Operating Voltage	V _{DDSYN}	4.75	5.25	V

Table A-14 25.17 MHz DC Characteristics (Continued)
 $(V_{DD} \text{ and } V_{DDSYN} = 5.0 \text{ Vdc} \pm 5\%, V_{SS} = 0 \text{ Vdc}, T_A = T_L \text{ to } T_H)$


Num	Characteristic	Symbol	Min	Max	Unit
14	V_{DDSYN} Supply Current ⁵ VCO on, 32.786 kHz crystal reference, maximum f_{sys} External Clock, maximum f_{sys} LPSTOP, 32.768 kHz crystal reference, VCO off (STSIM = 0) 32.768 kHz crystal, V_{DD} powered down	I_{DDSYN}	— — — —	2 6 150 100	mA mA μ A μ A
15	RAM Standby Voltage Specified V_{DD} applied $V_{DD} = V_{SS}$	V_{SB}	0.0 3.0	5.25 5.25	V
16	RAM Standby Current Normal RAM operation $V_{DD} > V_{SB} - 0.5V$ Transient condition $V_{SB} - 0.5V \leq V_{DD} \leq V_{SS} + 0.5V$ Standby operation $V_{DD} < V_{SS} + 0.5V$	I_{SB}	— — —	10 3 50	μ A mA μ A
17	Power Dissipation ⁷	P_D	—	766	mW
18	Input Capacitance ^{2, 8} All input-only pins All input/output pins	C_{IN}	— —	10 20	pF
19	Load Capacitance ² Group 1 I/O Pins, CLKOUT, FREEZE/QUOT, \overline{IPIPE} Group 2 I/O Pins and CSBOOT, BG/CS Group 3 I/O Pins Group 4 I/O Pins	C_L	— — — —	90 100 130 200	pF

NOTES:

- Applies to :
Port E[7:4] — $\overline{SIZ}[1:0]$, \overline{AS} , \overline{DS}
Port F[7:0] — $\overline{IRQ}[7:1]$, MODCLK
Port GP[7:0] — IC4/OC5/OC1, IC[3:1], OC[4:1]/OC1
Port QS[7:0] — TXD, PCS[3:1], PCS0/ \overline{SS} , SCK, MOSI, MISO
Other: BKPT/DSCLK, \overline{IFETCH} , \overline{RESET} , RXD, TSC, EXTAL (when PLL enabled)
- Input-Only Pins: EXTAL, TSC, BKPT/DSCLK, RXD
Output-Only Pins: CSBOOT, BG/CS, CLKOUT, FREEZE/QUOT, \overline{IPIPE}
Input/Output Pins:
Group 1: Port GP[7:0] — IC4/OC5/OC1, IC[3:1], OC[4:1]/OC1
Other: DATA[15:0], \overline{IFETCH}
Group 2: Port C[6:0] — ADDR[22:19]/CS[9:6], FC[2:0]/CS[5:3]
Port E[7:0] — $\overline{SIZ}[1:0]$, \overline{AS} , \overline{DS} , AVEC, RMC, $\overline{DSACK}[1:0]$
Port F[7:0] — $\overline{IRQ}[7:1]$, MODCLK
Port QS[7:3] — TXD, PCS[3:1], PCS0/ \overline{SS}
Other: ADDR23/CS10/ECLK, ADDR[18:0], R/W, \overline{BERR} , $\overline{BR}/CS0$, $\overline{BGACK}/CS2$
Group 3: \overline{HALT} , \overline{RESET}
Group 4: MISO, MOSI, SCK
- Does not apply to \overline{HALT} and \overline{RESET} because they are open drain pins. Does not apply to Port QS[7:0] (TXD, PCS[3:1], PCS0/ \overline{SS} , SCK, MOSI, MISO) in wired-OR mode.
- Current is measured at a specified system clock frequency, all modules active.
- Use of an active pulldown device is recommended.
- Total operating current is the sum of the appropriate I_{DD} , I_{DDSYN} values. I_{DD} values include supply currents for device modules powered by V_{DD} .
- Power dissipation is measured with external clock at maximum specified system clock frequency, all modules active. Power dissipation can be calculated using the following expression:
$$P_D = \text{Maximum } V_{DD} (I_{DD} + I_{DDSYN})$$

 I_{DD} includes supply currents for all device modules powered by V_{DD} pins.
- This parameter is periodically sampled rather than 100% tested.



Table A-15 Low Voltage 16.78 MHz AC Timing

(V_{DD} and $V_{DDSYN} = 3.0$ to 3.6 Vdc, $V_{SS} = 0$ Vdc, $T_A = T_L$ to T_H)¹

Num	Characteristic	Symbol	Min	Max	Unit
F1	Frequency of Operation	f_{sys}	DC	16.78	MHz
1	Clock Period	t_{cyc}	59.6	—	ns
1A	ECLK Period	t_{Ecyc}	476	—	ns
1B	External Clock Input Period ²	t_{xcyc}	59.6	—	ns
2, 3	Clock Pulse Width	t_{CW}	24	—	ns
2A, 3A	ECLK Pulse Width	t_{ECW}	236	—	ns
2B, 3B	External Clock Input High/Low Time ²	t_{xCHL}	29.8	—	ns
4, 5	CLKOUT Rise and Fall Time	t_{Crf}	—	7	ns
4A, 5A	Rise and Fall Time (All outputs except CLKOUT)	t_{rf}	—	8	ns
4B, 5B	External Clock Input Rise and Fall Time	t_{xCrf}	—	4	ns
6	Clock High to ADDR, FC, \overline{RMC} , SIZ Valid	t_{CHAV}	0	29	ns
7	Clock High to ADDR, Data, FC, \overline{RMC} , SIZ High Impedance	t_{CHAZx}	0	59	ns
8	Clock High to ADDR, FC, \overline{RMC} , SIZ Invalid	t_{CHAZn}	0	—	ns
9	Clock Low to \overline{AS} , \overline{DS} , \overline{CS} Asserted	t_{CLSA}	0	25	ns
9A	\overline{AS} to \overline{DS} or \overline{CS} Asserted (Read) ³	t_{STSA}	-15	15	ns
9C	Clock Low to \overline{IFETCH} , \overline{IPIPE} Asserted	t_{CLIA}	2	22	ns
11	ADDR, FC, \overline{RMC} , SIZ Valid to \overline{AS} , \overline{CS} , (and \overline{DS} Read) Asserted	t_{AVSA}	15	—	ns
12	Clock Low to \overline{AS} , \overline{DS} , \overline{CS} Negated	t_{CLSN}	2	29	ns
12A	Clock Low to \overline{IFETCH} , \overline{IPIPE} Negated	t_{CLIN}	2	29	ns
13	\overline{AS} , \overline{DS} , \overline{CS} Negated to ADDR, FC, SIZ Invalid (Address Hold)	t_{SNAI}	15	—	ns
14	\overline{AS} , \overline{CS} (and \overline{DS} Read) Width Asserted	t_{SWA}	100	—	ns
14A	\overline{DS} , \overline{CS} Width Asserted (Write)	t_{SWAW}	45	—	ns
14B	\overline{AS} , \overline{CS} (and \overline{DS} Read) Width Asserted (Fast Cycle)	t_{SWDW}	40	—	ns
15	\overline{AS} , \overline{DS} , \overline{CS} Width Negated ⁴	t_{SN}	40	—	ns
16	Clock High to \overline{AS} , \overline{DS} , R/W High Impedance	t_{CHSZ}	—	59	ns
17	\overline{AS} , \overline{DS} , \overline{CS} Negated to R/W High	t_{SNRN}	15	—	ns
18	Clock High to R/W High	t_{CHRH}	0	29	ns
20	Clock High to R/W Low	t_{CHRL}	0	29	ns
21	R/W High to \overline{AS} , \overline{CS} Asserted	t_{RAAA}	15	—	ns
22	R/W Low to \overline{DS} , \overline{CS} Asserted (Write)	t_{RASA}	70	—	ns
23	Clock High to Data Out Valid	t_{CHDO}	—	29	ns

Table A-15 Low Voltage 16.78 MHz AC Timing (Continued)
 $(V_{DD} \text{ and } V_{DDSYN} = 3.0 \text{ to } 3.6 \text{ Vdc}, V_{SS} = 0 \text{ Vdc}, T_A = T_L \text{ to } T_H)^1$


Num	Characteristic	Symbol	Min	Max	Unit
24	Data Out Valid to Negating Edge of \overline{AS} , \overline{CS} (Fast Write Cycle)	t_{DVASN}	15	—	ns
25	\overline{DS} , \overline{CS} Negated to Data Out Invalid (Data Out Hold)	$t_{SND OI}$	15	—	ns
26	Data Out Valid to \overline{DS} , \overline{CS} Asserted (Write)	t_{DVSA}	15	—	ns
27	Data In Valid to Clock Low (Data Setup)	t_{DICL}	5	—	ns
27A	Late \overline{BERR} , \overline{HALT} Asserted to Clock Low (Setup Time)	t_{BELCL}	20	—	ns
28	\overline{AS} , \overline{DS} Negated to $\overline{DSACK}[1:0]$, \overline{BERR} , \overline{HALT} , \overline{AVEC} Negated	t_{SNDN}	0	80	ns
29	\overline{DS} , \overline{CS} Negated to Data In Invalid (Data In Hold) ⁵	t_{SNDI}	0	—	ns
29A	\overline{DS} , \overline{CS} Negated to Data In High Impedance ^{5, 6}	t_{SHDI}	—	55	ns
30	CLKOUT Low to Data In Invalid (Fast Cycle Hold) ⁵	t_{CLDI}	10	—	ns
30A	CLKOUT Low to Data In High Impedance ⁵	t_{CLDH}	—	90	ns
31	$\overline{DSACK}[1:0]$ Asserted to Data In Valid ⁷	t_{DADI}	—	50	ns
33	Clock Low to \overline{BG} Asserted/Negated	t_{CLBAN}	—	29	ns
35	\overline{BR} Asserted to \overline{BG} Asserted (\overline{RMC} not Asserted) ⁸	t_{BRAGA}	1	—	t_{cyc}
37	\overline{BGACK} Asserted to \overline{BG} Negated	t_{GAGN}	1	2	t_{cyc}
39	\overline{BG} Width Negated	t_{GH}	2	—	t_{cyc}
39A	\overline{BG} Width Asserted	t_{GA}	1	—	t_{cyc}
46	R/ \overline{W} Width Asserted (Write or Read)	t_{RWA}	150	—	ns
46A	R/ \overline{W} Width Asserted (Fast Write or Read Cycle)	t_{RWAS}	90	—	ns
47A	Asynchronous Input Setup Time \overline{BR} , \overline{BGACK} , $\overline{DSACK}[1:0]$, \overline{BERR} , \overline{AVEC} , \overline{HALT}	t_{AIST}	5	—	ns
47B	Asynchronous Input Hold Time	t_{AIHT}	15	—	ns
48	$\overline{DSACK}[1:0]$ Asserted to \overline{BERR} , \overline{HALT} Asserted ⁹	t_{DABA}	—	30	ns
53	Data Out Hold from Clock High	t_{DOCH}	0	—	ns
54	Clock High to Data Out High Impedance	t_{CHDH}	—	28	ns
55	R/ \overline{W} Asserted to Data Bus Impedance Change	t_{RADC}	40	—	ns
70	Clock Low to Data Bus Driven (Show Cycle)	t_{SCLDD}	0	29	ns
71	Data Setup Time to Clock Low (Show Cycle)	t_{SCLDS}	15	—	ns
72	Data Hold from Clock Low (Show Cycle)	t_{SCLDH}	10	—	ns
73	\overline{BKPT} Input Setup Time	t_{BKST}	15	—	ns

Table A-15 Low Voltage 16.78 MHz AC Timing (Continued) $(V_{DD} \text{ and } V_{DDSYN} = 3.0 \text{ to } 3.6 \text{ Vdc}, V_{SS} = 0 \text{ Vdc}, T_A = T_L \text{ to } T_H)^1$

Num	Characteristic	Symbol	Min	Max	Unit
74	BKPT Input Hold Time	t_{BKHT}	10	—	ns
75	Mode Select Setup Time	t_{MSS}	20	—	t_{cyc}
76	Mode Select Hold Time	t_{MSH}	0	—	ns
77	RESET Assertion Time ¹⁰	t_{RSTA}	4	—	t_{cyc}
78	RESET Rise Time ^{11, 12}	t_{RSTR}	—	10	t_{cyc}

NOTES:

1. Refer to notes in [Table A-18](#).**Table A-16 16.78 MHz AC Timing** $(V_{DD} \text{ and } V_{DDSYN} = 5.0 \text{ Vdc} \pm 10\%, V_{SS} = 0 \text{ Vdc}, T_A = T_L \text{ to } T_H)^1$

Num	Characteristic	Symbol	Min	Max	Unit
F1	Frequency of Operation	f_{sys}	DC	16.78	MHz
1	Clock Period	t_{cyc}	59.6	—	ns
1A	ECLK Period	t_{Ecyc}	476	—	ns
1B	External Clock Input Period ²	t_{Xcyc}	59.6	—	ns
2, 3	Clock Pulse Width	t_{CW}	24	—	ns
2A, 3A	ECLK Pulse Width	t_{ECW}	236	—	ns
2B, 3B	External Clock Input High/Low Time ²	t_{XCHL}	29.8	—	ns
4, 5	CLKOUT Rise and Fall Time	t_{Crf}	—	5	ns
4A, 5A	Rise and Fall Time (All outputs except CLKOUT)	t_{rf}	—	8	ns
4B, 5B	External Clock Input Rise and Fall Time	t_{XCrf}	—	5	ns
6	Clock High to ADDR, FC, \overline{RMC} , SIZ Valid	t_{CHAV}	0	29	ns
7	Clock High to ADDR, Data, FC, \overline{RMC} , SIZ High Impedance	t_{CHAZx}	0	59	ns
8	Clock High to ADDR, FC, \overline{RMC} , SIZ Invalid	t_{CHAZn}	0	—	ns
9	Clock Low to \overline{AS} , \overline{DS} , \overline{CS} Asserted	t_{CLSA}	2	25	ns
9A	\overline{AS} to \overline{DS} or \overline{CS} Asserted (Read) ³	t_{STSA}	-15	15	ns
9C	Clock Low to \overline{IFETCH} , \overline{IPIPE} Asserted	t_{CLIA}	2	22	ns
11	ADDR, FC, \overline{RMC} , SIZ Valid to \overline{AS} , \overline{CS} , (and \overline{DS} Read) Asserted	t_{AVSA}	15	—	ns
12	Clock Low to \overline{AS} , \overline{DS} , \overline{CS} Negated	t_{CLSN}	2	29	ns
12A	Clock Low to \overline{IFETCH} , \overline{IPIPE} Negated	t_{CLIN}	2	22	ns
13	\overline{AS} , \overline{DS} , \overline{CS} Negated to ADDR, FC, SIZ Invalid (Address Hold)	t_{SNAI}	15	—	ns
14	\overline{AS} , \overline{CS} (and \overline{DS} Read) Width Asserted	t_{SWA}	100	—	ns
14A	\overline{DS} , \overline{CS} Width Asserted (Write)	t_{SWAW}	45	—	ns
14B	\overline{AS} , \overline{CS} (and \overline{DS} Read) Width Asserted (Fast Cycle)	t_{SWDW}	40	—	ns
15	\overline{AS} , \overline{DS} , \overline{CS} Width Negated ⁴	t_{SN}	40	—	ns
16	Clock High to \overline{AS} , \overline{DS} , R/W High Impedance	t_{CHSZ}	—	59	ns
17	\overline{AS} , \overline{DS} , \overline{CS} Negated to R/W High	t_{SNRN}	15	—	ns
18	Clock High to R/W High	t_{CHRH}	0	29	ns
20	Clock High to R/W Low	t_{CHRL}	0	29	ns
21	R/W High to \overline{AS} , \overline{CS} Asserted	t_{RAAA}	15	—	ns



Table A-16 16.78 MHz AC Timing (Continued) $(V_{DD} \text{ and } V_{DDSYN} = 5.0 \text{ Vdc} \pm 10\%, V_{SS} = 0 \text{ Vdc}, T_A = T_L \text{ to } T_H)^1$ 

Num	Characteristic	Symbol	Min	Max	Unit
22	R/W Low to \overline{DS} , \overline{CS} Asserted (Write)	t_{RASA}	70	—	ns
23	Clock High to Data Out Valid	t_{CHDO}	—	29	ns
24	Data Out Valid to Negating Edge of \overline{AS} , \overline{CS} (Fast Write Cycle)	t_{DVASN}	15	—	ns
25	\overline{DS} , \overline{CS} Negated to Data Out Invalid (Data Out Hold)	$t_{SND OI}$	15	—	ns
26	Data Out Valid to \overline{DS} , \overline{CS} Asserted (Write)	t_{DVSA}	15	—	ns
27	Data In Valid to Clock Low (Data Setup)	t_{DICL}	5	—	ns
27A	Late \overline{BERR} , \overline{HALT} Asserted to Clock Low (Setup Time)	t_{BELCL}	20	—	ns
28	\overline{AS} , \overline{DS} Negated to $\overline{DSACK}[1:0]$, \overline{BERR} , \overline{HALT} , \overline{AVEC} Negated	t_{SNDN}	0	80	ns
29	\overline{DS} , \overline{CS} Negated to Data In Invalid (Data In Hold) ⁵	t_{SNDI}	0	—	ns
29A	\overline{DS} , \overline{CS} Negated to Data In High Impedance ^{5, 6}	t_{SHDI}	—	55	ns
30	CLKOUT Low to Data In Invalid (Fast Cycle Hold) ⁵	t_{CLDI}	15	—	ns
30A	CLKOUT Low to Data In High Impedance ⁵	t_{CLDH}	—	90	ns
31	$\overline{DSACK}[1:0]$ Asserted to Data In Valid ⁷	t_{DADI}	—	50	ns
33	Clock Low to \overline{BG} Asserted/Negated	t_{CLBAN}	—	29	ns
35	\overline{BR} Asserted to \overline{BG} Asserted (\overline{RMC} not Asserted) ⁸	t_{BRAGA}	1	—	t_{cyc}
37	\overline{BGACK} Asserted to \overline{BG} Negated	t_{GAGN}	1	2	t_{cyc}
39	\overline{BG} Width Negated	t_{GH}	2	—	t_{cyc}
39A	\overline{BG} Width Asserted	t_{GA}	1	—	t_{cyc}
46	R/W Width Asserted (Write or Read)	t_{RWA}	150	—	ns
46A	R/W Width Asserted (Fast Write or Read Cycle)	t_{RWAS}	90	—	ns
47A	Asynchronous Input Setup Time \overline{BR} , \overline{BGACK} , $\overline{DSACK}[1:0]$, \overline{BERR} , \overline{AVEC} , \overline{HALT}	t_{AIST}	5	—	ns
47B	Asynchronous Input Hold Time	t_{AIHT}	15	—	ns
48	$\overline{DSACK}[1:0]$ Asserted to \overline{BERR} , \overline{HALT} Asserted ⁹	t_{DABA}	—	30	ns
53	Data Out Hold from Clock High	t_{DOCH}	0	—	ns
54	Clock High to Data Out High Impedance	t_{CHDH}	—	28	ns
55	R/W Asserted to Data Bus Impedance Change	t_{RADC}	40	—	ns
56	\overline{RESET} Pulse Width (Reset Instruction)	t_{HRPW}	512	—	t_{cyc}
57	\overline{BERR} Negated to \overline{HALT} Negated (Rerun)	t_{BNHN}	0	—	ns
70	Clock Low to Data Bus Driven (Show Cycle)	t_{SCLDD}	0	29	ns
71	Data Setup Time to Clock Low (Show Cycle)	t_{SCLDS}	15	—	ns
72	Data Hold from Clock Low (Show Cycle)	t_{SCLDH}	10	—	ns
73	\overline{BKPT} Input Setup Time	t_{BKST}	15	—	ns

Table A-16 16.78 MHz AC Timing (Continued) $(V_{DD} \text{ and } V_{DDSYN} = 5.0 \text{ Vdc} \pm 10\%, V_{SS} = 0 \text{ Vdc}, T_A = T_L \text{ to } T_H)^1$

Num	Characteristic	Symbol	Min	Max	Unit
74	BKPT Input Hold Time	t_{BKHT}	10	—	ns
75	Mode Select Setup Time	t_{MSS}	20	—	t_{cyc}
76	Mode Select Hold Time	t_{MSH}	0	—	ns
77	RESET Assertion Time ¹⁰	t_{RSTA}	4	—	t_{cyc}
78	RESET Rise Time ^{11, 12}	t_{RSTR}	—	10	t_{cyc}

NOTES:

1. Refer to notes in [Table A-18](#).**Table A-17 20.97 MHz AC Timing** $(V_{DD} \text{ and } V_{DDSYN} = 5.0 \text{ Vdc} \pm 5\%, V_{SS} = 0 \text{ Vdc}, T_A = T_L \text{ to } T_H)^1$

Num	Characteristic	Symbol	Min	Max	Unit
F1	Frequency of Operation	f_{sys}	DC	20.97	MHz
1	Clock Period	t_{cyc}	47.7	—	ns
1A	ECLK Period	t_{Ecyc}	381	—	ns
1B	External Clock Input Period ²	t_{Xcyc}	47.7	—	ns
2, 3	Clock Pulse Width	t_{CW}	18.8	—	ns
2A, 3A	ECLK Pulse Width	t_{ECW}	183	—	ns
2B, 3B	External Clock Input High/Low Time ²	t_{XCHL}	23.8	—	ns
4, 5	CLKOUT Rise and Fall Time	t_{Crf}	—	5	ns
4A, 5A	Rise and Fall Time (All outputs except CLKOUT)	t_{rf}	—	8	ns
4B, 5B	External Clock Input Rise and Fall Time	t_{XCrf}	—	5	ns
6	Clock High to ADDR, FC, \overline{RMC} , SIZ Valid	t_{CHAV}	0	23	ns
7	Clock High to ADDR, Data, FC, \overline{RMC} , SIZ High Impedance	t_{CHAZx}	0	47	ns
8	Clock High to ADDR, FC, \overline{RMC} , SIZ Invalid	t_{CHAZn}	0	—	ns
9	Clock Low to \overline{AS} , \overline{DS} , \overline{CS} Asserted	t_{CLSA}	0	23	ns
9A	\overline{AS} to \overline{DS} or \overline{CS} Asserted (Read) ³	t_{STSA}	-10	10	ns
9C	Clock Low to \overline{IFETCH} , \overline{IPIPE} Asserted	t_{CLIA}	2	22	ns
11	ADDR, FC, \overline{RMC} , SIZ Valid to \overline{AS} , \overline{CS} , (and \overline{DS} Read) Asserted	t_{AVSA}	10	—	ns
12	Clock Low to \overline{AS} , \overline{DS} , \overline{CS} Negated	t_{CLSN}	2	23	ns
12A	Clock Low to \overline{IFETCH} , \overline{IPIPE} Negated	t_{CLIN}	2	22	ns
13	\overline{AS} , \overline{DS} , \overline{CS} Negated to ADDR, FC, SIZ Invalid (Address Hold)	t_{SNAI}	10	—	ns
14	\overline{AS} , \overline{CS} (and \overline{DS} Read) Width Asserted	t_{SWA}	80	—	ns
14A	\overline{DS} , \overline{CS} Width Asserted (Write)	t_{SWAW}	36	—	ns
14B	\overline{AS} , \overline{CS} (and \overline{DS} Read) Width Asserted (Fast Cycle)	t_{SWDW}	32	—	ns
15	\overline{AS} , \overline{DS} , \overline{CS} Width Negated ⁴	t_{SN}	32	—	ns
16	Clock High to \overline{AS} , \overline{DS} , \overline{CS} High Impedance	t_{CHSZ}	—	47	ns
17	\overline{AS} , \overline{DS} , \overline{CS} Negated to R/W High	t_{SNRN}	10	—	ns
18	Clock High to R/W High	t_{CHRH}	0	23	ns
20	Clock High to R/W Low	t_{CHRL}	0	23	ns
21	R/W High to \overline{AS} , \overline{CS} Asserted	t_{RAAA}	10	—	ns

Table A-17 20.97 MHz AC Timing (Continued)(V_{DD} and V_{DDSYN} = 5.0 Vdc ± 5%, V_{SS} = 0 Vdc, T_A = T_L to T_H)¹

Num	Characteristic	Symbol	Min	Max	Unit
22	R/W Low to \overline{DS} , \overline{CS} Asserted (Write)	t _{RASA}	54	—	ns
23	Clock High to Data Out Valid	t _{CHDO}	—	23	ns
24	Data Out Valid to Negating Edge of \overline{AS} , \overline{CS} (Fast Write Cycle)	t _{DVASN}	10	—	ns
25	\overline{DS} , \overline{CS} Negated to Data Out Invalid (Data Out Hold)	t _{SNDIO}	10	—	ns
26	Data Out Valid to \overline{DS} , \overline{CS} Asserted (Write)	t _{DVSA}	10	—	ns
27	Data In Valid to Clock Low (Data Setup)	t _{DICL}	5	—	ns
27A	Late \overline{BERR} , \overline{HALT} Asserted to Clock Low (Setup Time)	t _{BELCL}	15	—	ns
28	\overline{AS} , \overline{DS} Negated to $\overline{DSACK}[1:0]$, \overline{BERR} , \overline{HALT} , \overline{AVEC} Negated	t _{SNDN}	0	60	ns
29	\overline{DS} , \overline{CS} Negated to Data In Invalid (Data In Hold) ⁵	t _{SNDI}	0	—	ns
29A	\overline{DS} , \overline{CS} Negated to Data In High Impedance ^{5, 6}	t _{SHDI}	—	48	ns
30	CLKOUT Low to Data In Invalid (Fast Cycle Hold) ⁵	t _{CLDI}	10	—	ns
30A	CLKOUT Low to Data In High Impedance ⁵	t _{CLDH}	—	72	ns
31	$\overline{DSACK}[1:0]$ Asserted to Data In Valid ⁷	t _{DADI}	—	46	ns
33	Clock Low to \overline{BG} Asserted/Negated	t _{CLBAN}	—	23	ns
35	\overline{BR} Asserted to \overline{BG} Asserted (\overline{RMC} not Asserted) ⁸	t _{BRAGA}	1	—	t _{cyc}
37	\overline{BGACK} Asserted to \overline{BG} Negated	t _{GAGN}	1	2	t _{cyc}
39	\overline{BG} Width Negated	t _{GH}	2	—	t _{cyc}
39A	\overline{BG} Width Asserted	t _{GA}	1	—	t _{cyc}
46	R/W Width Asserted (Write or Read)	t _{RWA}	115	—	ns
46A	R/W Width Asserted (Fast Write or Read Cycle)	t _{RWAS}	70	—	ns
47A	Asynchronous Input Setup Time \overline{BR} , \overline{BGACK} , $\overline{DSACK}[1:0]$, \overline{BERR} , \overline{AVEC} , \overline{HALT}	t _{AIST}	5	—	ns
47B	Asynchronous Input Hold Time	t _{AIHT}	12	—	ns
48	$\overline{DSACK}[1:0]$ Asserted to \overline{BERR} , \overline{HALT} Asserted ⁹	t _{DABA}	—	30	ns
53	Data Out Hold from Clock High	t _{DOCH}	0	—	ns
54	Clock High to Data Out High Impedance	t _{CHDH}	—	23	ns
55	R/W Asserted to Data Bus Impedance Change	t _{RADC}	32	—	ns
56	\overline{RESET} Pulse Width (Reset Instruction)	t _{HRPW}	512	—	t _{cyc}
57	\overline{BERR} Negated to \overline{HALT} Negated (Rerun)	t _{BNHN}	0	—	ns
70	Clock Low to Data Bus Driven (Show Cycle)	t _{SCLDD}	0	29	ns
71	Data Setup Time to Clock Low (Show Cycle)	t _{SCLDS}	10	—	ns
72	Data Hold from Clock Low (Show Cycle)	t _{SCLDH}	10	—	ns
73	\overline{BKPT} Input Setup Time	t _{BKST}	10	—	ns
74	\overline{BKPT} Input Hold Time	t _{BKHT}	10	—	ns
75	Mode Select Setup Time	t _{MSS}	20	—	t _{cyc}
76	Mode Select Hold Time	t _{MSH}	0	—	ns
77	\overline{RESET} Assertion Time ¹⁰	t _{RSTA}	4	—	t _{cyc}
78	\overline{RESET} Rise Time ^{11, 12}	t _{RSTR}	—	10	t _{cyc}

NOTES:

1. Refer to notes in [Table A-18](#).



Table A-18 25.17 MHz AC Timing

(V_{DD} and $V_{DDSYN} = 5.0 \text{ Vdc} \pm 5\%$, $V_{SS} = 0 \text{ Vdc}$, $T_A = T_L \text{ to } T_H$)¹

Num	Characteristic	Symbol	Min	Max	Unit
F1	Frequency of Operation	f_{sys}	DC	25.17	MHz
1	Clock Period	t_{cyc}	39.7	—	ns
1A	ECLK Period	t_{Ecyc}	318	—	ns
1B	External Clock Input Period ²	t_{Xcyc}	39.7	—	ns
2, 3	Clock Pulse Width	t_{CW}	15	—	ns
2A, 3A	ECLK Pulse Width	t_{ECW}	155	—	ns
2B, 3B	External Clock Input High/Low Time ²	t_{XCHL}	19.8	—	ns
4, 5	CLKOUT Rise and Fall Time	t_{CrF}	—	5	ns
4A, 5A	Rise and Fall Time (All outputs except CLKOUT)	t_{rF}	—	8	ns
4B, 5B	External Clock Input Rise and Fall Time	t_{XCrf}	—	4	ns
6	Clock High to ADDR, FC, \overline{RMC} , SIZ Valid	t_{CHAV}	0	19	ns
7	Clock High to ADDR, Data, FC, \overline{RMC} , SIZ High Impedance	t_{CHAZx}	0	39	ns
8	Clock High to ADDR, FC, \overline{RMC} , SIZ Invalid	t_{CHAZn}	0	—	ns
9	Clock Low to \overline{AS} , \overline{DS} , \overline{CS} Asserted	t_{CLSA}	0	19	ns
9A	\overline{AS} to \overline{DS} or \overline{CS} Asserted (Read) ³	t_{STSA}	-10	10	ns
9C	Clock Low to \overline{IFETCH} , \overline{IPIPE} Asserted	t_{CLIA}	2	19	ns
11	ADDR, FC, \overline{RMC} , SIZ Valid to \overline{AS} , \overline{CS} , (and \overline{DS} Read) Asserted	t_{AVSA}	8	—	ns
12	Clock Low to \overline{AS} , \overline{DS} , \overline{CS} Negated	t_{CLSN}	2	19	ns
12A	Clock Low to \overline{IFETCH} , \overline{IPIPE} Negated	t_{CLIN}	2	19	ns
13	\overline{AS} , \overline{DS} , \overline{CS} Negated to ADDR, FC, SIZ Invalid (Address Hold)	t_{SNAI}	8	—	ns
14	\overline{AS} , \overline{CS} (and \overline{DS} Read) Width Asserted	t_{SWA}	65	—	ns
14A	\overline{DS} , \overline{CS} Width Asserted (Write)	t_{SWAW}	25	—	ns
14B	\overline{AS} , \overline{CS} (and \overline{DS} Read) Width Asserted (Fast Cycle)	t_{SWDW}	22	—	ns
15	\overline{AS} , \overline{DS} , \overline{CS} Width Negated ⁴	t_{SN}	22	—	ns
16	Clock High to \overline{AS} , \overline{DS} , R/W High Impedance	t_{CHSZ}	—	39	ns
17	\overline{AS} , \overline{DS} , \overline{CS} Negated to R/W High	t_{SNRN}	10	—	ns
18	Clock High to R/W High	t_{CHRH}	0	19	ns
20	Clock High to R/W Low	t_{CHRL}	0	19	ns
21	R/W High to \overline{AS} , \overline{CS} Asserted	t_{RAAA}	10	—	ns
22	R/W Low to \overline{DS} , \overline{CS} Asserted (Write)	t_{RASA}	40	—	ns
23	Clock High to Data Out Valid	t_{CHDO}	—	19	ns
24	Data Out Valid to Negating Edge of \overline{AS} , \overline{CS} (Fast Write Cycle)	t_{DVASN}	7	—	ns
25	\overline{DS} , \overline{CS} Negated to Data Out Invalid (Data Out Hold)	t_{SNDOI}	5	—	ns
26	Data Out Valid to \overline{DS} , \overline{CS} Asserted (Write)	t_{DVSA}	8	—	ns
27	Data In Valid to Clock Low (Data Setup)	t_{DICL}	5	—	ns
27A	Late \overline{BERR} , \overline{HALT} Asserted to Clock Low (Setup Time)	t_{BELCL}	10	—	ns
28	\overline{AS} , \overline{DS} Negated to $\overline{DSACK}[1:0]$, \overline{BERR} , \overline{HALT} , \overline{AVEC} Negated	t_{SNDN}	0	50	ns
29	\overline{DS} , \overline{CS} Negated to Data In Invalid (Data In Hold) ⁵	t_{SNDI}	0	—	ns
29A	\overline{DS} , \overline{CS} Negated to Data In High Impedance ^{5, 6}	t_{SHDI}	—	45	ns
30	CLKOUT Low to Data In Invalid (Fast Cycle Hold) ⁵	t_{CLDI}	8	—	ns

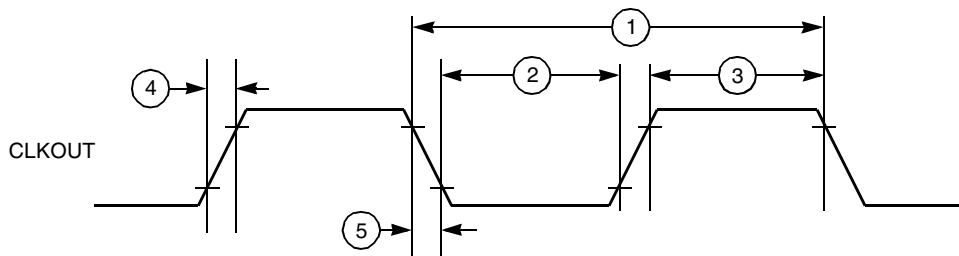
Table A-18 25.17 MHz AC Timing (Continued)(V_{DD} and V_{DDSYN} = 5.0 Vdc ± 5%, V_{SS} = 0 Vdc, T_A = T_L to T_H)¹

Num	Characteristic	Symbol	Min	Max	Unit
30A	CLKOUT Low to Data In High Impedance ⁵	t _{CLDH}	—	60	ns
31	$\overline{DSACK}[1:0]$ Asserted to Data In Valid ⁷	t _{DADI}	—	35	ns
33	Clock Low to \overline{BG} Asserted/Negated	t _{CLBAN}	—	19	ns
35	\overline{BR} Asserted to \overline{BG} Asserted (\overline{RMC} not Asserted) ⁸	t _{BRAGA}	1	—	t _{cyc}
37	\overline{BGACK} Asserted to \overline{BG} Negated	t _{GAGN}	1	2	t _{cyc}
39	\overline{BG} Width Negated	t _{GH}	2	—	t _{cyc}
39A	\overline{BG} Width Asserted	t _{GA}	1	—	t _{cyc}
46	R/ \overline{W} Width Asserted (Write or Read)	t _{RWA}	90	—	ns
46A	R/ \overline{W} Width Asserted (Fast Write or Read Cycle)	t _{RWAS}	55	—	ns
47A	Asynchronous Input Setup Time \overline{BR} , \overline{BGACK} , $\overline{DSACK}[1:0]$, \overline{BERR} , \overline{AVEC} , \overline{HALT}	t _{AIST}	5	—	ns
47B	Asynchronous Input Hold Time	t _{AIHT}	10	—	ns
48	$\overline{DSACK}[1:0]$ Asserted to \overline{BERR} , \overline{HALT} Asserted ⁹	t _{DABA}	—	27	ns
53	Data Out Hold from Clock High	t _{DOCH}	0	—	ns
54	Clock High to Data Out High Impedance	t _{CHDH}	—	23	ns
55	R/ \overline{W} Asserted to Data Bus Impedance Change	t _{RADC}	25	—	ns
56	\overline{RESET} Pulse Width (Reset Instruction)	t _{HRPW}	512	—	t _{cyc}
57	\overline{BERR} Negated to \overline{HALT} Negated (Rerun)	t _{BNHN}	0	—	ns
70	Clock Low to Data Bus Driven (Show Cycle)	t _{SCLDD}	0	19	ns
71	Data Setup Time to Clock Low (Show Cycle)	t _{SCLDS}	8	—	ns
72	Data Hold from Clock Low (Show Cycle)	t _{SCLDH}	8	—	ns
73	\overline{BKPT} Input Setup Time	t _{BKST}	10	—	ns
74	\overline{BKPT} Input Hold Time	t _{BKHT}	10	—	ns
75	Mode Select Setup Time	t _{MSS}	20	—	t _{cyc}
76	Mode Select Hold Time	t _{MSH}	0	—	ns
77	\overline{RESET} Assertion Time ¹⁰	t _{RSTA}	4	—	t _{cyc}
78	\overline{RESET} Rise Time ^{11, 12}	t _{RSTR}	—	10	t _{cyc}

NOTES:

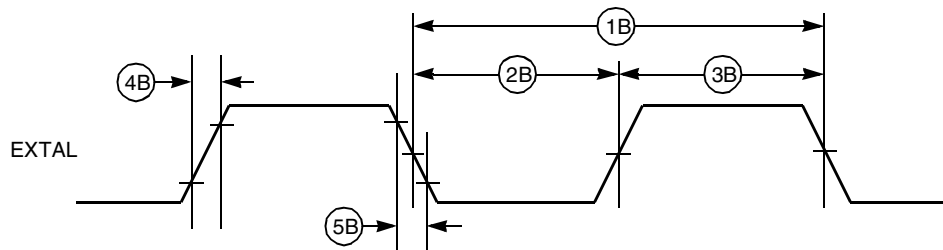
1. All AC timing is shown with respect to V_{IH}/V_{IL} levels unless otherwise noted.
2. When an external clock is used, minimum high and low times are based on a 50% duty cycle. The minimum allowable t_{x_{cyc}} period is reduced when the duty cycle of the external clock varies. The relationship between external clock input duty cycle and minimum t_{x_{cyc}} is expressed:
Minimum t_{x_{cyc}} period = minimum t_{x_{CHL}} / (50% – external clock input duty cycle tolerance).
3. Specification 9A is the worst-case skew between \overline{AS} and \overline{DS} or \overline{CS} . The amount of skew depends on the relative loading of these signals. When loads are kept within specified limits, skew will not cause \overline{AS} and \overline{DS} to fall outside the limits shown in specification 9.
4. If multiple chip-selects are used, \overline{CS} width negated (specification 15) applies to the time from the negation of a heavily loaded chip-select to the assertion of a lightly loaded chip select. The \overline{CS} width negated specification between multiple chip-selects does not apply to chip selects being used for synchronous ECLK cycles.
5. Hold times are specified with respect to \overline{DS} or \overline{CS} on asynchronous reads and with respect to CLKOUT on fast cycle reads. The user is free to use either hold time.
6. Maximum value is equal to (t_{cyc} / 2) + 25 ns.
7. If the asynchronous setup time (specification 47A) requirements are satisfied, the $\overline{DSACK}[1:0]$ low to data setup time (specification 31) and $\overline{DSACK}[1:0]$ low to \overline{BERR} low setup time (specification 48) can be ignored. The data must only satisfy the data-in to clock low setup time (specification 27) for the following clock cycle. \overline{BERR} must satisfy only the late \overline{BERR} low to clock low setup time (specification 27A) for the following clock cycle.

8. To ensure coherency during every operand transfer, \overline{BG} is not asserted in response to \overline{BR} until after all cycles of the current operand transfer are complete.
9. In the absence of $DSACK[1:0]$, $BERR$ is an asynchronous input using the asynchronous setup time (specification 47A).
10. After external \overline{RESET} negation is detected, a short transition period (approximately $2 t_{cyc}$) elapses, then the SIM drives \overline{RESET} low for $512 t_{cyc}$.
11. External assertion of the \overline{RESET} input can overlap internally-generated resets. To insure that an external reset is recognized in all cases, \overline{RESET} must be asserted for at least 590 CLKOUT cycles.
12. External logic must pull \overline{RESET} high during this period in order for normal MCU operation to begin.



68300 CLKOUT TIM

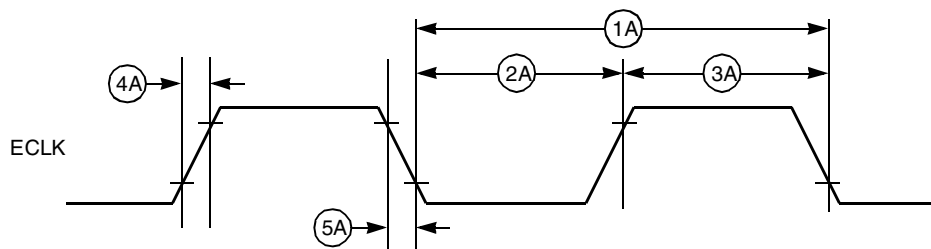
Figure A-1 CLKOUT Output Timing Diagram



NOTE: PULSE WIDTH SHOWN WITH RESPECT TO 50% V_{DD} .

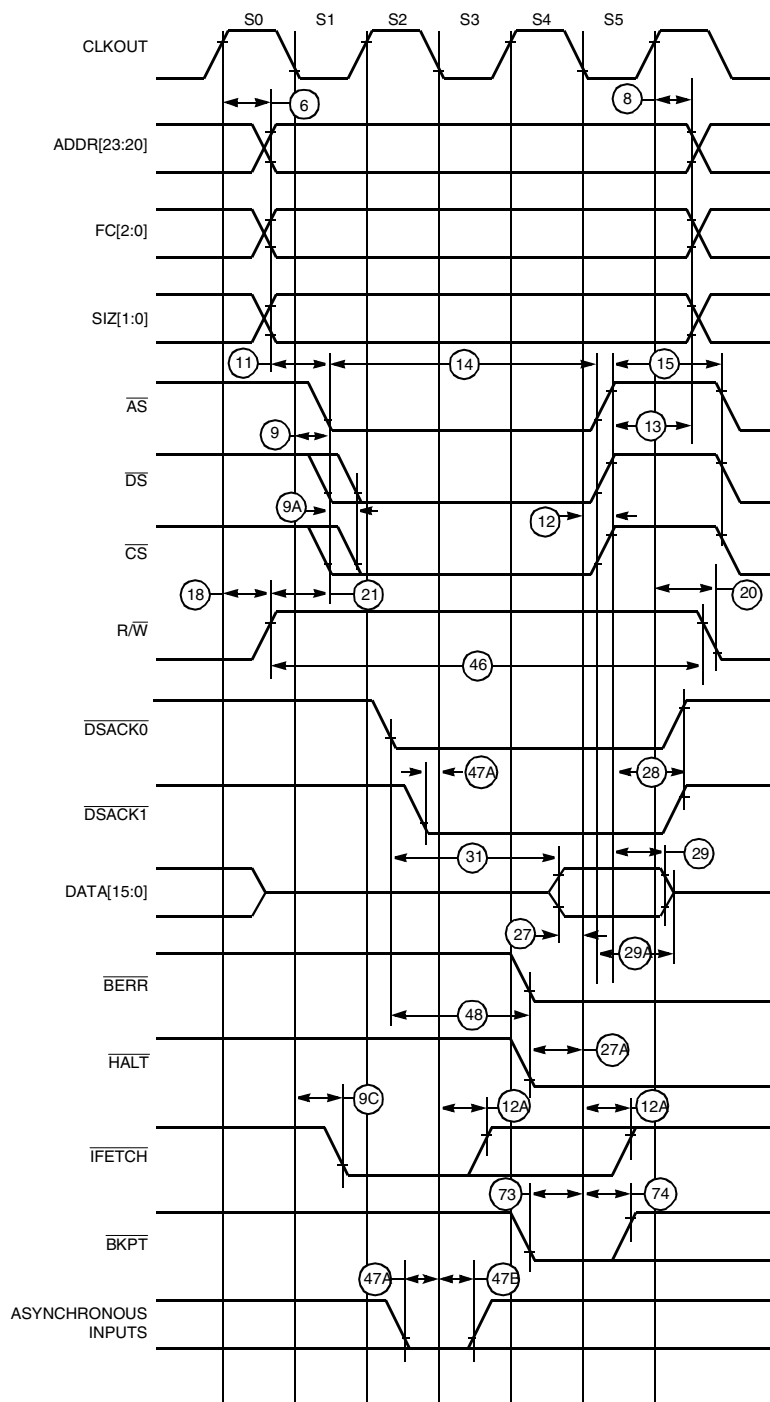
68300 EXT CLK INPUT TIM

Figure A-2 External Clock Input Timing Diagram



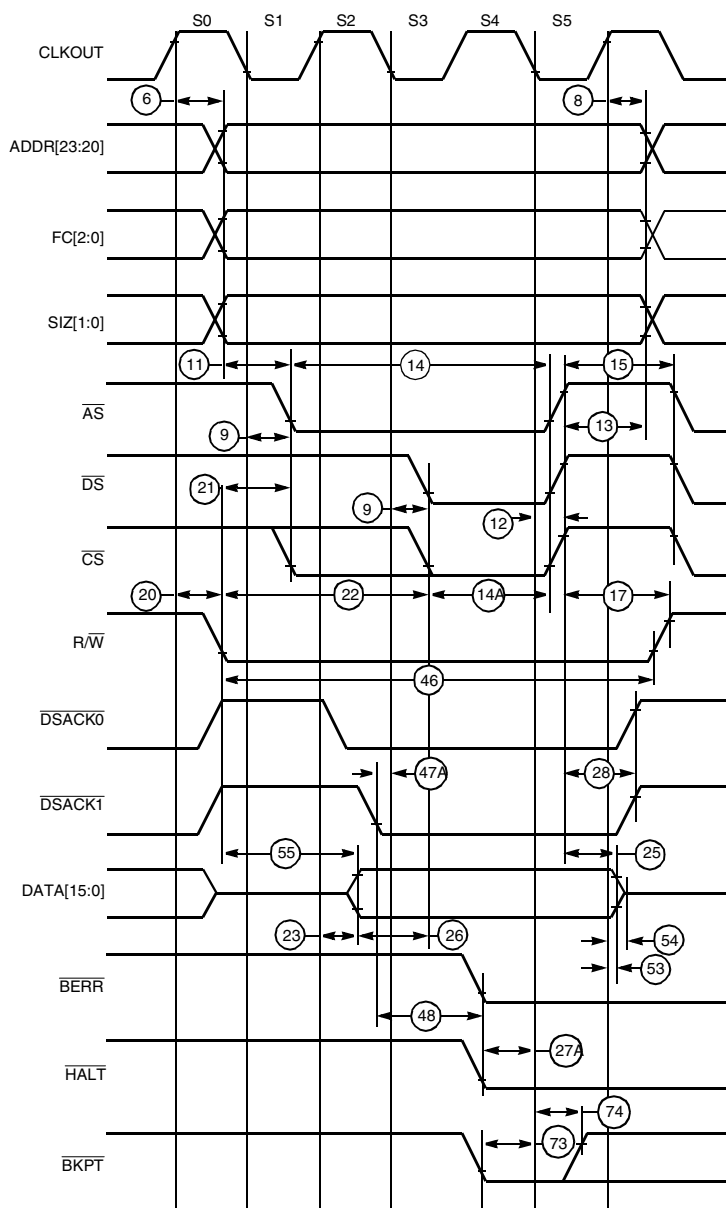
68300 ECLK OUTPUT TIM

Figure A-3 ECLK Output Timing Diagram



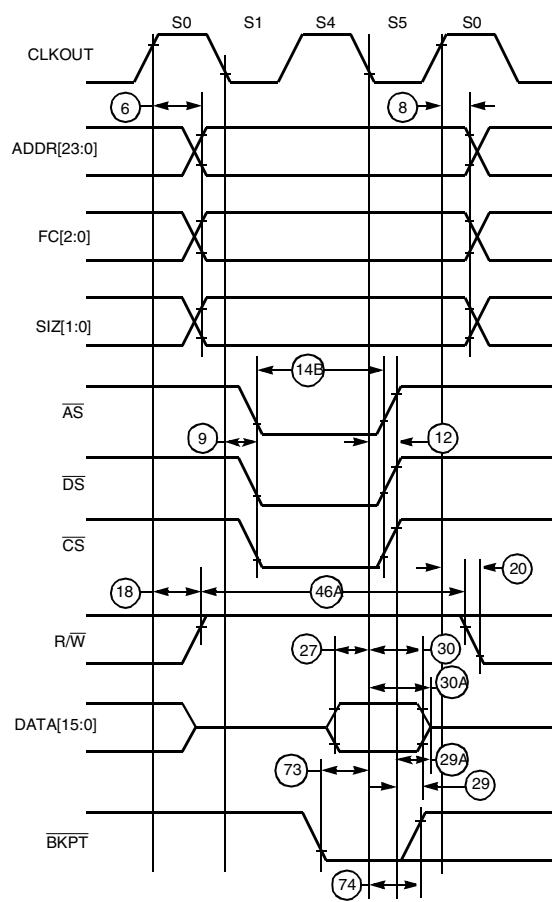
68300 RD CYC TIM

Figure A-4 Read Cycle Timing Diagram



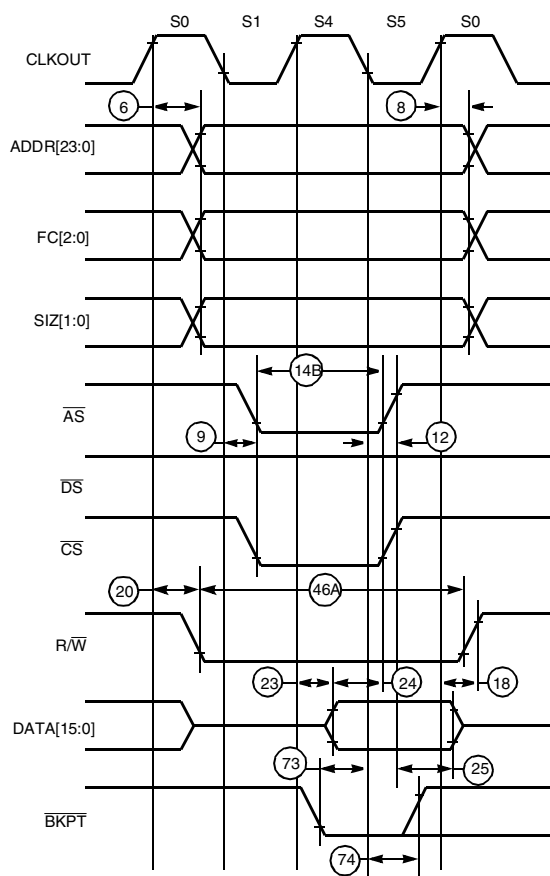
68300 WR CYC TIM

Figure A-5 Write Cycle Timing Diagram



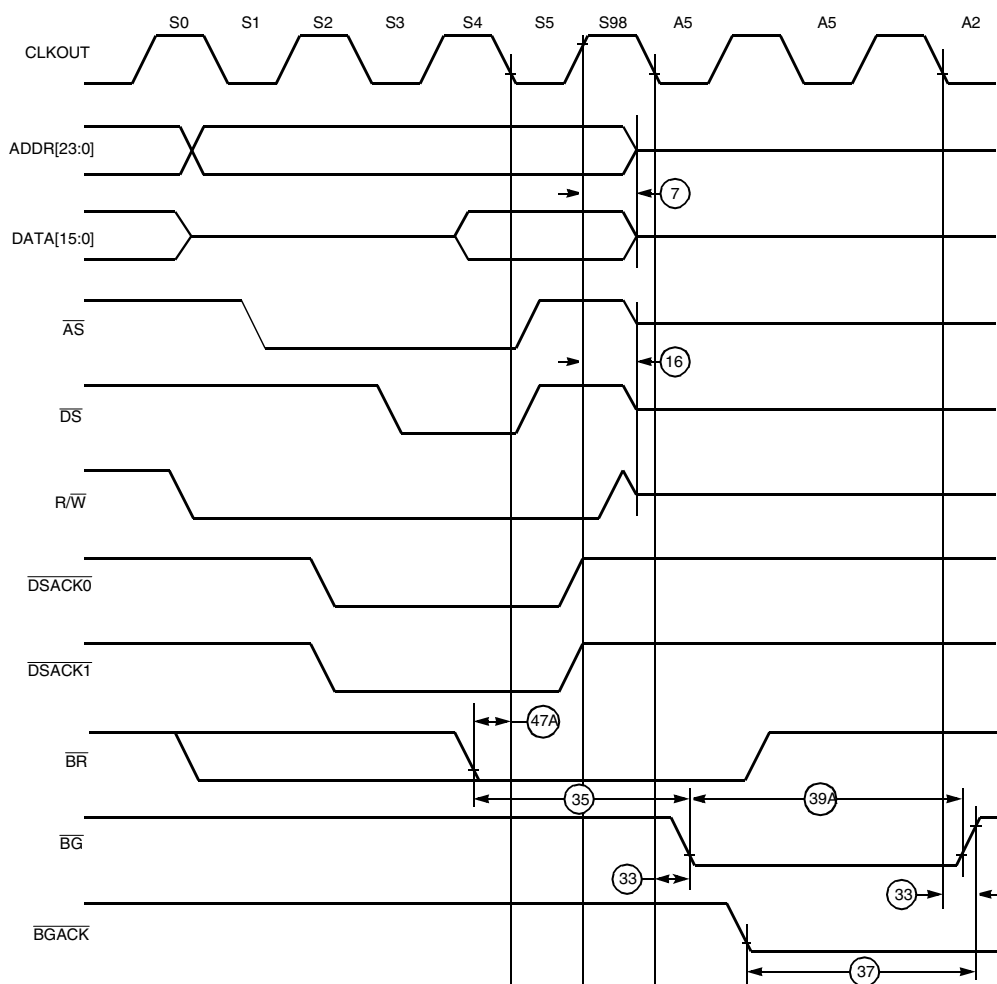
68300 FAST RD CYC TIM

Figure A-6 Fast Termination Read Cycle Timing Diagram



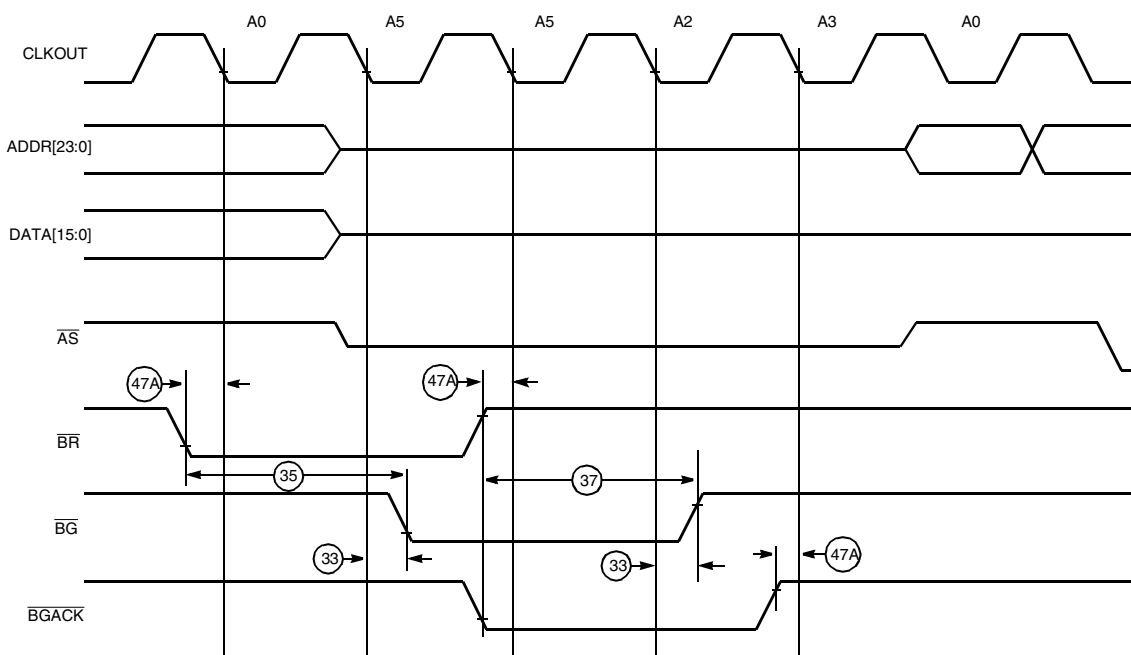
68300 FAST WR CYC TIM

Figure A-7 Fast Termination Write Cycle Timing Diagram



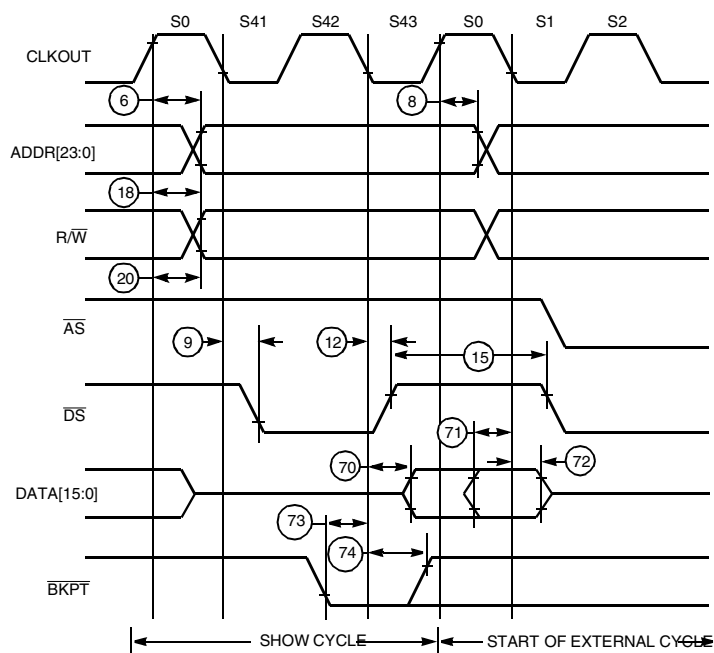
68300 BUS ARB TIM

Figure A-8 Bus Arbitration Timing Diagram — Active Bus Case



68300 BUS ARB TIM IDLE

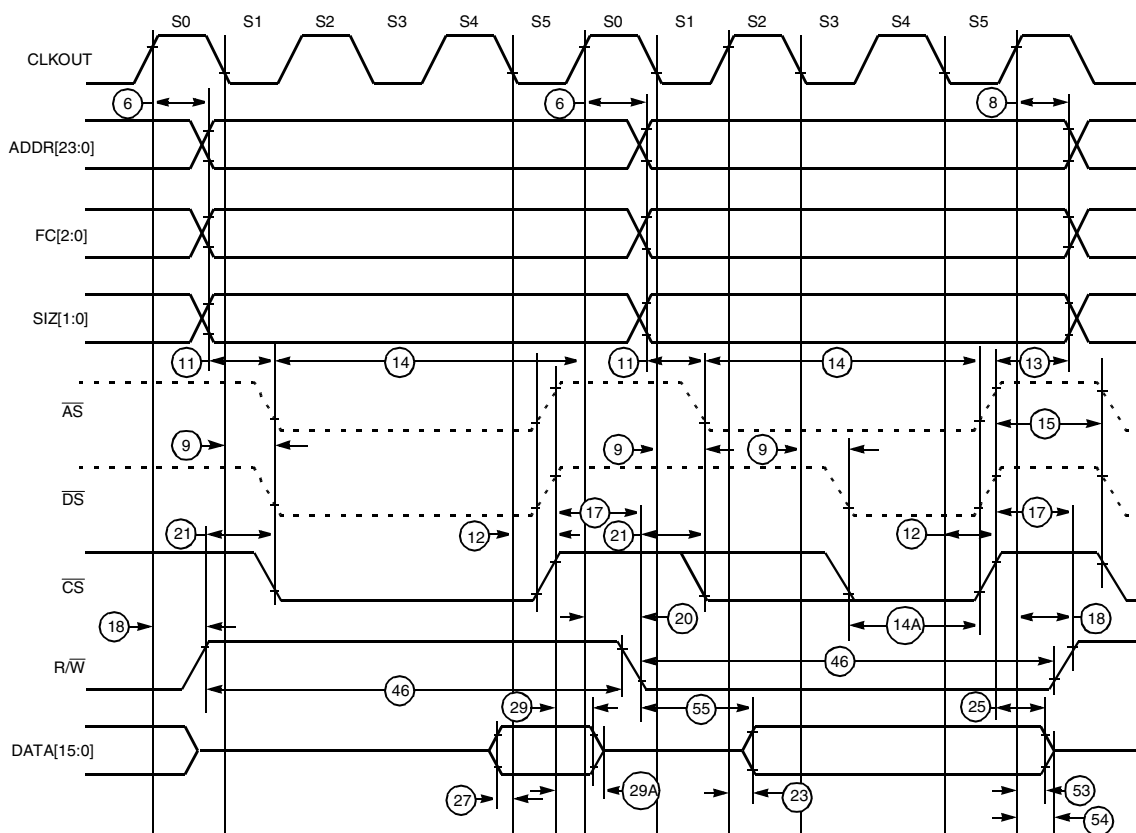
Figure A-9 Bus Arbitration Timing Diagram — Idle Bus Case



NOTE:
SHOW CYCLES CAN STRETCH DURING CLOCK PHASE S42 WHEN BUS ACCESSES TAKE LONGER THAN TWO CYCLES DUE TO IMB MODULE WAIT-STATE INSERTION.

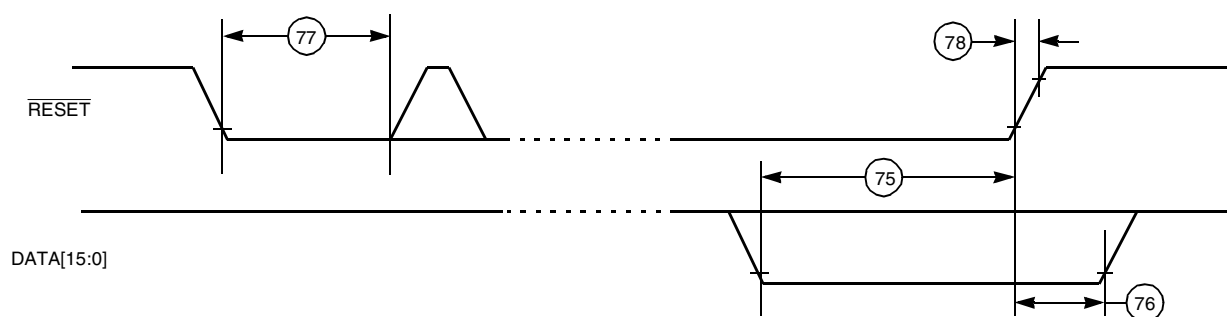
68300 SHW CYC TIM

Figure A-10 Show Cycle Timing Diagram



68300 CHIP SEL TIM

Figure A-11 Chip-Select Timing Diagram



68300 RST/MODE SEL TIM

Figure A-12 Reset and Mode Select Timing Diagram



Table A-19 Low Voltage Background Debugging Mode Timing

(V_{DD} and $V_{DDSYN} = 3.0$ to 3.6 Vdc, $V_{SS} = 0$ Vdc, $T_A = T_L$ to T_H)¹

Num	Characteristic	Symbol	Min	Max	Unit
B0	DSI Input Setup Time	t_{DSISU}	15	—	ns
B1	DSI Input Hold Time	t_{DSIH}	10	—	ns
B2	DSCLK Setup Time	t_{DSCSU}	15	—	ns
B3	DSCLK Hold Time	t_{DSCH}	10	—	ns
B4	DSO Delay Time	t_{DSOD}	—	25	ns
B5	DSCLK Cycle Time	t_{DSCCYC}	2	—	t_{cyc}
B6	CLKOUT Low to FREEZE Asserted/Negated	t_{FRZAN}	—	50	ns
B7	CLKOUT High to \overline{IFETCH} High Impedance	t_{IPZ}	—	50	ns
B8	CLKOUT High to \overline{IFETCH} Valid	t_{IP}	—	50	ns
B9	DSCLK Low Time	t_{DSCLO}	1	—	t_{cyc}

NOTES:

1. All AC timing is shown with respect to V_{IH}/V_{IL} levels unless otherwise noted.

Table A-20 16.78 MHz Background Debug Mode Timing

(V_{DD} and $V_{DDSYN} = 5$ Vdc \pm 5%, $V_{SS} = 0$ Vdc, $T_A = T_L$ to T_H)¹

Num	Characteristic	Symbol	Min	Max	Unit
B0	DSI Input Setup Time	t_{DSISU}	15	—	ns
B1	DSI Input Hold Time	t_{DSIH}	10	—	ns
B2	DSCLK Setup Time	t_{DSCSU}	15	—	ns
B3	DSCLK Hold Time	t_{DSCH}	10	—	ns
B4	DSO Delay Time	t_{DSOD}	—	25	ns
B5	DSCLK Cycle Time	t_{DSCCYC}	2	—	t_{cyc}
B6	CLKOUT Low to FREEZE Asserted/Negated	t_{FRZAN}	—	50	ns
B7	CLKOUT High to \overline{IFETCH} High Impedance	t_{IPZ}	—	TBD	ns
B8	CLKOUT High to \overline{IFETCH} Valid	t_{IP}	—	TBD	ns
B9	DSCLK Low Time	t_{DSCLO}	1	—	t_{cyc}

NOTES:

1. All AC timing is shown with respect to V_{IH}/V_{IL} levels unless otherwise noted.



Table A-21 20.97 MHz Background Debug Mode Timing

(V_{DD} and $V_{DDSYN} = 5 \text{ Vdc} \pm 5\%$, $V_{SS} = 0 \text{ Vdc}$, $T_A = T_L$ to T_H)¹

Num	Characteristic	Symbol	Min	Max	Unit
B0	DSI Input Setup Time	t_{DSISU}	15	—	ns
B1	DSI Input Hold Time	t_{DSIH}	10	—	ns
B2	DSCLK Setup Time	t_{DSCSU}	15	—	ns
B3	DSCLK Hold Time	t_{DSCH}	10	—	ns
B4	DSO Delay Time	t_{DSOD}	—	25	ns
B5	DSCLK Cycle Time	t_{DSCCYC}	2	—	t_{cyc}
B6	CLKOUT Low to FREEZE Asserted/Negated	t_{FRZAN}	—	50	ns
B7	CLKOUT High to $\overline{\text{IFETCH}}$ High Impedance	t_{IPZ}	—	TBD	ns
B8	CLKOUT High to $\overline{\text{IFETCH}}$ Valid	t_{IP}	—	TBD	ns
B9	DSCLK Low Time	t_{DSCLO}	1	—	t_{cyc}

NOTES:

1. All AC timing is shown with respect to V_{IH}/V_{IL} levels unless otherwise noted.

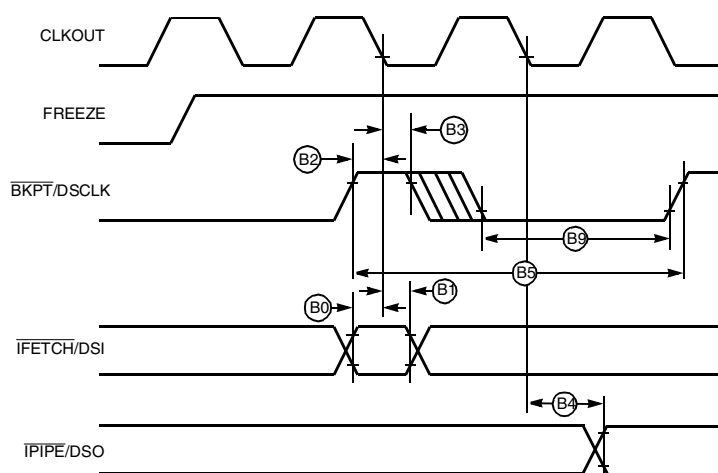
Table A-22 25.17 MHz Background Debug Mode Timing

(V_{DD} and $V_{DDSYN} = 5 \text{ Vdc} \pm 5\%$, $V_{SS} = 0 \text{ Vdc}$, $T_A = T_L$ to T_H)¹

Num	Characteristic	Symbol	Min	Max	Unit
B0	DSI Input Setup Time	t_{DSISU}	10	—	ns
B1	DSI Input Hold Time	t_{DSIH}	5	—	ns
B2	DSCLK Setup Time	t_{DSCSU}	10	—	ns
B3	DSCLK Hold Time	t_{DSCH}	5	—	ns
B4	DSO Delay Time	t_{DSOD}	—	20	ns
B5	DSCLK Cycle Time	t_{DSCCYC}	2	—	t_{cyc}
B6	CLKOUT Low to FREEZE Asserted/Negated	t_{FRZAN}	—	30	ns
B7	CLKOUT High to $\overline{\text{IFETCH}}$ High Impedance	t_{IPZ}	—	30	ns
B8	CLKOUT High to $\overline{\text{IFETCH}}$ Valid	t_{IP}	—	30	ns
B9	DSCLK Low Time	t_{DSCLO}	1	—	t_{cyc}

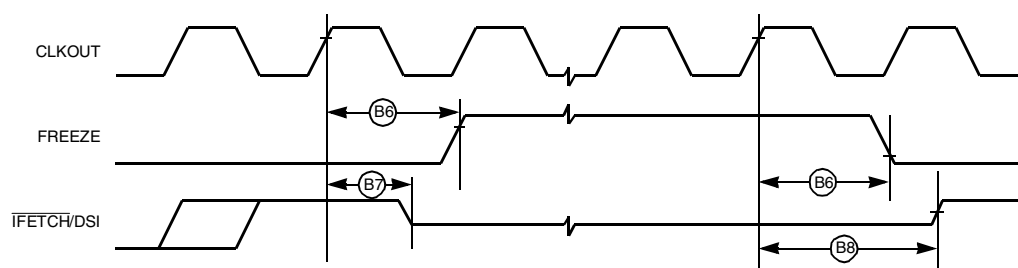
NOTES:

1. All AC timing is shown with respect to V_{IH}/V_{IL} levels unless otherwise noted.



68300 BKGD DBM SER COM TIM

Figure A-13 BDM Serial Communication Timing Diagram



68300 BDM FRZ TIM

Figure A-14 BDM Freeze Assertion Timing Diagram



Table A-23 Low Voltage ECLK Bus Timing

(V_{DD} and $V_{DDSYN} = 3.0$ to 3.6 Vdc, $V_{SS} = 0$ Vdc, $T_A = T_L$ to T_H)¹

Num	Characteristic	Symbol	Min	Max	Unit
E1	ECLK Low to Address Valid ²	t_{EAD}	—	60	ns
E2	ECLK Low to Address Hold	t_{EAH}	15	—	ns
E3	ECLK Low to \overline{CS} Valid (\overline{CS} Delay)	t_{ECSD}	—	150	ns
E4	ECLK Low to \overline{CS} Hold	t_{ECSH}	15	—	ns
E5	\overline{CS} Negated Width	t_{ECSN}	30	—	ns
E6	Read Data Setup Time	t_{EDSR}	30	—	ns
E7	Read Data Hold Time	t_{EDHR}	5	—	ns
E8	ECLK Low to Data High Impedance	t_{EDHZ}	—	60	ns
E9	\overline{CS} Negated to Data Hold (Read)	t_{ECDH}	0	—	ns
E10	\overline{CS} Negated to Data High Impedance	t_{ECDZ}	—	1	t_{cyc}
E11	ECLK Low to Data Valid (Write)	t_{EDDW}	—	2	t_{cyc}
E12	ECLK Low to Data Hold (Write)	t_{EDHW}	15	—	ns
E13	Address Access Time (Read) ³	t_{EACC}	386	—	ns
E14	Chip-Select Access Time (Read) ⁴	t_{EACS}	296	—	ns
E15	Address Setup Time	t_{EAS}	1/2	—	t_{cyc}

NOTES:

1. Refer to notes in [Table A-26](#).



Table A-24 16.78 MHz ECLK Bus Timing

(V_{DD} and $V_{DDSYN} = 5 \text{ Vdc} \pm 5\%$, $V_{SS} = 0 \text{ Vdc}$, $T_A = T_L$ to T_H)¹

Num	Characteristic	Symbol	Min	Max	Unit
E1	ECLK Low to Address Valid ²	t_{EAD}	—	60	ns
E2	ECLK Low to Address Hold	t_{EAH}	15	—	ns
E3	ECLK Low to \overline{CS} Valid (\overline{CS} Delay)	$t_{ECS D}$	—	150	ns
E4	ECLK Low to \overline{CS} Hold	$t_{ECS H}$	15	—	ns
E5	\overline{CS} Negated Width	$t_{ECS N}$	30	—	ns
E6	Read Data Setup Time	t_{EDSR}	30	—	ns
E7	Read Data Hold Time	t_{EDHR}	5	—	ns
E8	ECLK Low to Data High Impedance	t_{EDHZ}	—	60	ns
E9	\overline{CS} Negated to Data Hold (Read)	t_{ECDH}	0	—	ns
E10	\overline{CS} Negated to Data High Impedance	t_{ECDZ}	—	1	t_{cyc}
E11	ECLK Low to Data Valid (Write)	t_{EDDW}	—	2	t_{cyc}
E12	ECLK Low to Data Hold (Write)	t_{EDHW}	15	—	ns
E13	Address Access Time (Read) ³	t_{EACC}	386	—	ns
E14	Chip-Select Access Time (Read) ⁴	t_{EACS}	296	—	ns
E15	Address Setup Time	t_{EAS}	1/2	—	t_{cyc}

NOTES:

1. Refer to notes in [Table A-26](#).

**Table A-25 20.97 MHz ECLK Bus Timing**

(V_{DD} and $V_{DDSYN} = 5 \text{ Vdc} \pm 5\%$, $V_{SS} = 0 \text{ Vdc}$, $T_A = T_L$ to T_H)¹

Num	Characteristic	Symbol	Min	Max	Unit
E1	ECLK Low to Address Valid ²	t_{EAD}	—	48	ns
E2	ECLK Low to Address Hold	t_{EAH}	10	—	ns
E3	ECLK Low to \overline{CS} Valid (\overline{CS} Delay)	$t_{ECS D}$	—	120	ns
E4	ECLK Low to \overline{CS} Hold	$t_{ECS H}$	10	—	ns
E5	\overline{CS} Negated Width	$t_{ECS N}$	25	—	ns
E6	Read Data Setup Time	t_{EDSR}	25	—	ns
E7	Read Data Hold Time	t_{EDHR}	5	—	ns
E8	ECLK Low to Data High Impedance	t_{EDHZ}	—	48	ns
E9	\overline{CS} Negated to Data Hold (Read)	t_{ECDH}	0	—	ns
E10	\overline{CS} Negated to Data High Impedance	t_{ECDZ}	—	1	t_{cyc}
E11	ECLK Low to Data Valid (Write)	t_{EDDW}	—	2	t_{cyc}
E12	ECLK Low to Data Hold (Write)	t_{EDHW}	10	—	ns
E13	Address Access Time (Read) ³	t_{EACC}	308	—	ns
E14	Chip-Select Access Time (Read) ⁴	t_{EACS}	236	—	ns
E15	Address Setup Time	t_{EAS}	1/2	—	t_{cyc}

NOTES:

1. Refer to notes in [Table A-26](#).



Table A-26 25.17 MHz ECLK Bus Timing

(V_{DD} and $V_{DDSYN} = 5 \text{ Vdc} \pm 5\%$, $V_{SS} = 0 \text{ Vdc}$, $T_A = T_L$ to T_H)¹

Num	Characteristic	Symbol	Min	Max	Unit
E1	ECLK Low to Address Valid ²	t_{EAD}	—	40	ns
E2	ECLK Low to Address Hold	t_{EAH}	10	—	ns
E3	ECLK Low to \overline{CS} Valid (\overline{CS} Delay)	$t_{ECS D}$	—	100	ns
E4	ECLK Low to \overline{CS} Hold	$t_{ECS H}$	10	—	ns
E5	\overline{CS} Negated Width	$t_{ECS N}$	20	—	ns
E6	Read Data Setup Time	t_{EDSR}	25	—	ns
E7	Read Data Hold Time	t_{EDHR}	5	—	ns
E8	ECLK Low to Data High Impedance	t_{EDHZ}	—	40	ns
E9	\overline{CS} Negated to Data Hold (Read)	t_{ECDH}	0	—	ns
E10	\overline{CS} Negated to Data High Impedance	t_{ECDZ}	—	1	t_{cyc}
E11	ECLK Low to Data Valid (Write)	t_{EDDW}	—	2	t_{cyc}
E12	ECLK Low to Data Hold (Write)	t_{EDHW}	5	—	ns
E13	Address Access Time (Read) ³	t_{EACC}	255	—	ns
E14	Chip-Select Access Time (Read) ⁴	t_{EACS}	195	—	ns
E15	Address Setup Time	t_{EAS}	1/2	—	t_{cyc}

NOTES:

1. All AC timing is shown with respect to V_{IH}/V_{IL} levels unless otherwise noted.
2. When previous bus cycle is not an ECLK cycle, the address may be valid before ECLK goes low.
3. Address access time = $t_{Ecyc} - t_{EAD} - t_{EDSR}$.
4. Chip select access time = $t_{Ecyc} - t_{ECS D} - t_{EDSR}$.

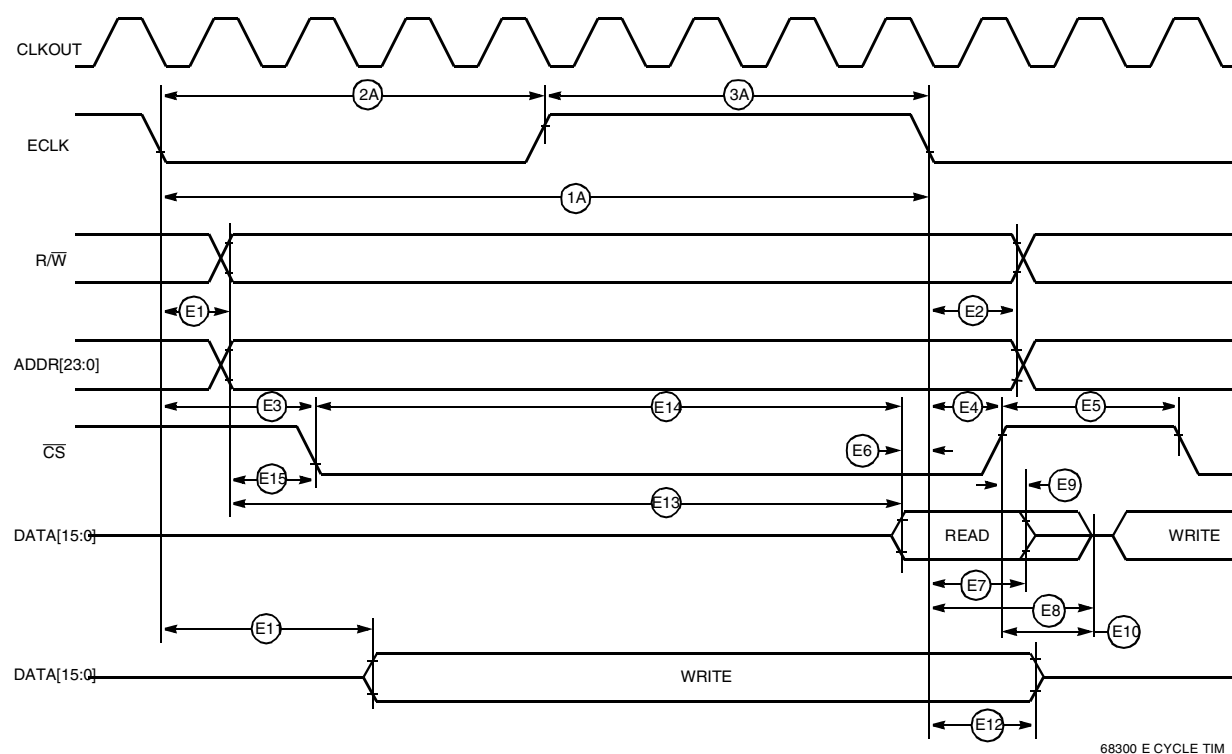


Figure A-15 ECLK Timing Diagram



Table A-27 Low Voltage QSPI Timing

(V_{DD} and $V_{DDSYN} = 3.0$ to 3.6 Vdc, $V_{SS} = 0$ Vdc, $T_A = T_L$ to T_H , 100 pF load on all QSPI pins)¹

Num	Function	Symbol	Min	Max	Unit
	Operating Frequency Master Slave	f_{qspi}	DC DC	1/4 1/4	f_{sys} f_{sys}
1	Cycle Time Master Slave	t_{qcyt}	4 4	510 —	t_{cyc} t_{cyc}
2	Enable Lead Time Master Slave	t_{lead}	2 2	128 —	t_{cyc} t_{cyc}
3	Enable Lag Time Master Slave	t_{lag}	— 2	1/2 —	SCK t_{cyc}
4	Clock (SCK) High or Low Time Master Slave ²	t_{sw}	$2 t_{cyc} - 60$ $2 t_{cyc} - n$	$255 t_{cyc}$ —	ns ns
5	Sequential Transfer Delay Master Slave (Does Not Require Deselect)	t_{td}	17 13	8192 —	t_{cyc} t_{cyc}
6	Data Setup Time (Inputs) Master Slave	t_{su}	30 20	— —	ns ns
7	Data Hold Time (Inputs) Master Slave	t_{hi}	0 20	— —	ns ns
8	Slave Access Time	t_a	—	1	t_{cyc}
9	Slave MISO Disable Time	t_{dis}	—	2	t_{cyc}
10	Data Valid (after SCK Edge) Master Slave	t_v	— —	50 50	ns ns
11	Data Hold Time (Outputs) Master Slave	t_{ho}	0 0	— —	ns ns
12	Rise Time Input Output	t_{ri} t_{ro}	— —	2 30	μs ns
13	Fall Time Input Output	t_{fi} t_{fo}	— —	2 30	μs ns

NOTES:

1. Refer to notes in [Table A-29](#).



Table A-28 16.78 MHz/20.97 MHz QSPI Timing

(V_{DD} and $V_{DDSYN} = 5 \text{ Vdc} \pm 5\%$, $V_{SS} = 0 \text{ Vdc}$, $T_A = T_L$ to T_H , 200 pF load on all QSPI pins)¹

Num	Function	Symbol	Min	Max	Unit
	Operating Frequency Master Slave	f_{qspi}	DC DC	1/4 1/4	f_{sys} f_{sys}
1	Cycle Time Master Slave	t_{qcyt}	4 4	510 —	t_{cyc} t_{cyc}
2	Enable Lead Time Master Slave	t_{lead}	2 2	128 —	t_{cyc} t_{cyc}
3	Enable Lag Time Master Slave	t_{lag}	— 2	1/2 —	SCK t_{cyc}
4	Clock (SCK) High or Low Time Master Slave ²	t_{sw}	$2 t_{cyc} - 60$ $2 t_{cyc} - n$	$255 t_{cyc}$ —	ns ns
5	Sequential Transfer Delay Master Slave (Does Not Require Deselect)	t_{td}	17 13	8192 —	t_{cyc} t_{cyc}
6	Data Setup Time (Inputs) Master Slave	t_{su}	30 20	— —	ns ns
7	Data Hold Time (Inputs) Master Slave	t_{hi}	0 20	— —	ns ns
8	Slave Access Time	t_a	—	1	t_{cyc}
9	Slave MISO Disable Time	t_{dis}	—	2	t_{cyc}
10	Data Valid (after SCK Edge) Master Slave	t_v	— —	50 50	ns ns
11	Data Hold Time (Outputs) Master Slave	t_{ho}	0 0	— —	ns ns
12	Rise Time Input Output	t_{ri} t_{ro}	— —	2 30	μs ns
13	Fall Time Input Output	t_{fi} t_{fo}	— —	2 30	μs ns

NOTES:

1. Refer to notes in [Table A-29](#).



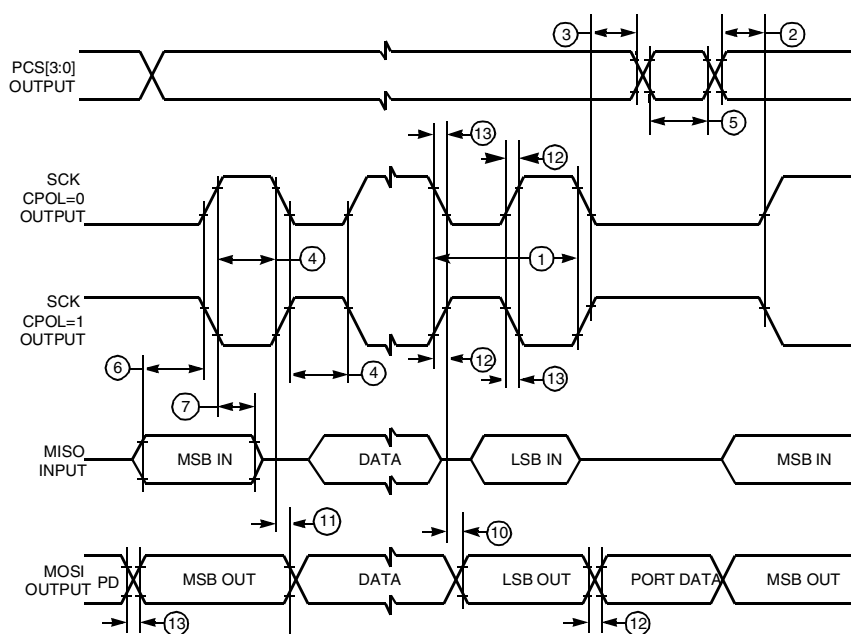
Table A-29 25.17 MHz QSPI Timing

(V_{DD} and $V_{DDSYN} = 5 \text{ Vdc} \pm 5\%$, $V_{SS} = 0 \text{ Vdc}$, $T_A = T_L$ to T_H , 200 pF load on all QSPI pins)¹

Num	Function	Symbol	Min	Max	Unit
	Operating Frequency Master Slave	f_{qspi}	DC DC	1/4 1/4	f_{sys} f_{sys}
1	Cycle Time Master Slave	t_{qcyt}	4 4	510 —	t_{cyc} t_{cyc}
2	Enable Lead Time Master Slave	t_{lead}	2 2	128 —	t_{cyc} t_{cyc}
3	Enable Lag Time Master Slave	t_{lag}	— 2	1/2 —	SCK t_{cyc}
4	Clock (SCK) High or Low Time Master Slave ²	t_{sw}	$2 t_{cyc} - 30$ $2 t_{cyc} - n$	$255 t_{cyc}$ —	ns ns
5	Sequential Transfer Delay Master Slave (Does Not Require Deselect)	t_{td}	17 13	8192 —	t_{cyc} t_{cyc}
6	Data Setup Time (Inputs) Master Slave	t_{su}	20 20	— —	ns ns
7	Data Hold Time (Inputs) Master Slave	t_{hi}	0 20	— —	ns ns
8	Slave Access Time	t_a	—	1	t_{cyc}
9	Slave MISO Disable Time	t_{dis}	—	2	t_{cyc}
10	Data Valid (after SCK Edge) Master Slave	t_v	— —	50 50	ns ns
11	Data Hold Time (Outputs) Master Slave	t_{ho}	0 0	— —	ns ns
12	Rise Time Input Output	t_{ri} t_{ro}	— —	2 30	μs ns
13	Fall Time Input Output	t_{fi} t_{fo}	— —	2 30	μs ns

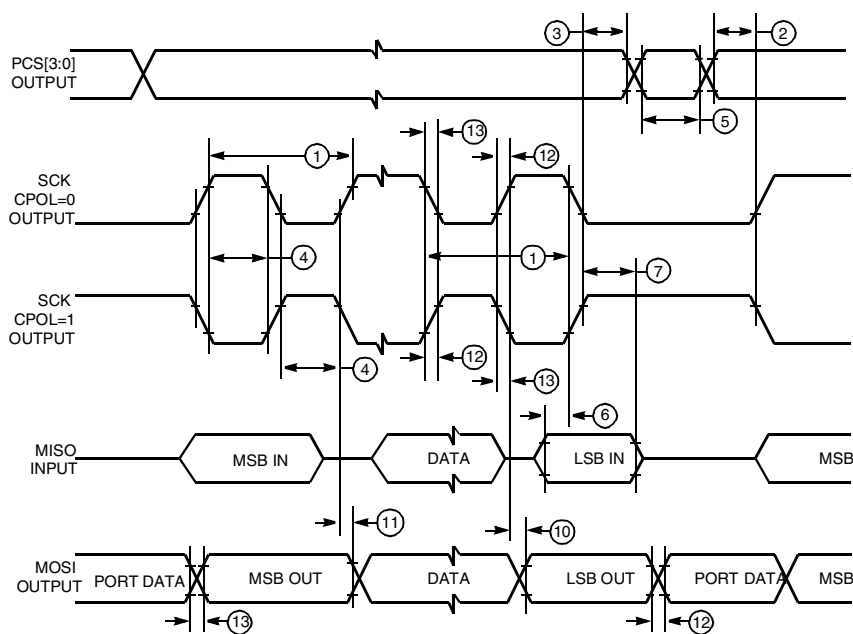
NOTES:

1. All AC timing is shown with respect to V_{IH}/V_{IL} levels unless otherwise noted.
2. For high time, n = External SCK rise time; for low time, n = External SCK fall time.



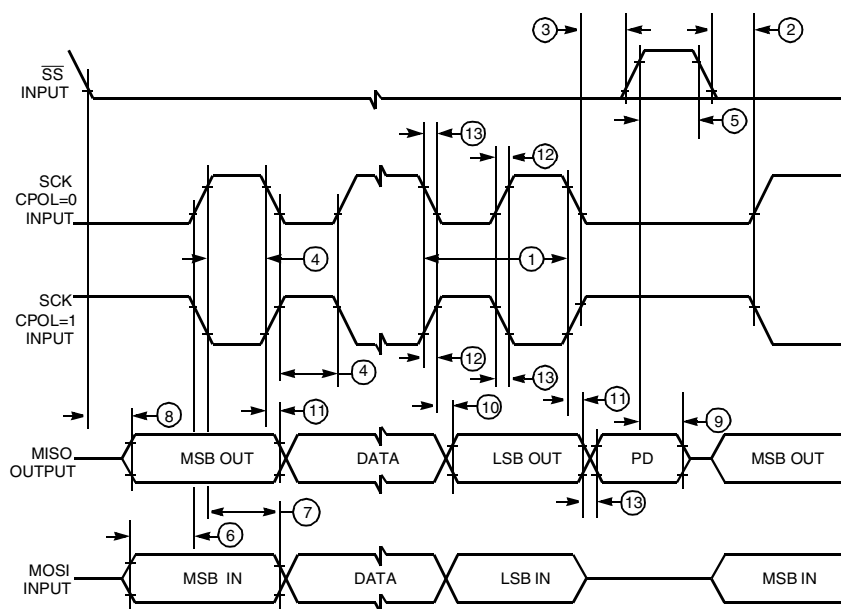
68300 QSPI MAST CPHA0

Figure A-16 QSPI Timing — Master, CPHA = 0



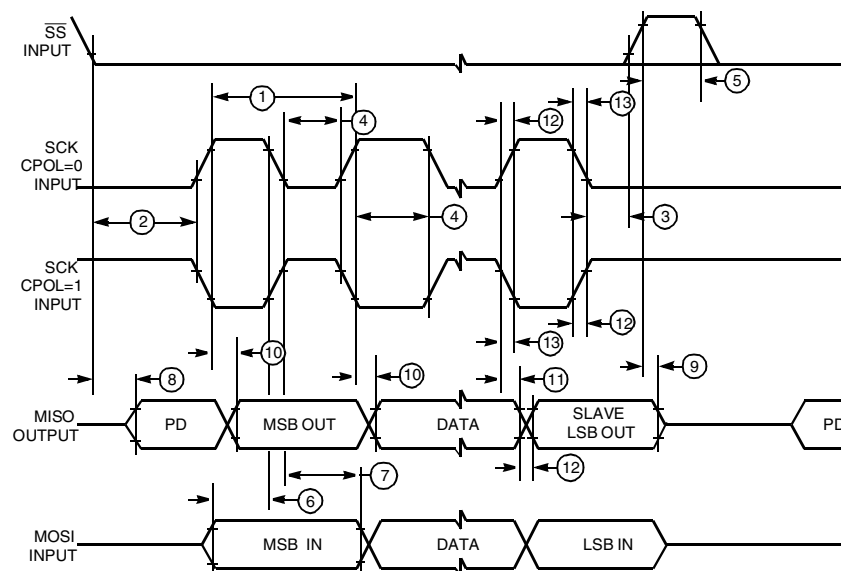
68300 QSPI MAST CPHA1

Figure A-17 QSPI Timing — Master, CPHA = 1



68300 QSPI SLV CPHA0

Figure A-18 QSPI Timing — Slave, CPHA = 0



68300 QSPI SLV CPHA1

Figure A-19 QSPI Timing — Slave, CPHA = 1

**Table A-30 Low Voltage TPU Timing** $(V_{DD} \text{ and } V_{DDA} = 3.0 \text{ to } 3.6\text{Vdc}, V_{SS} = 0 \text{ Vdc}, T_A = T_L \text{ to } T_H)^{1, 2}$

Num	Parameter	Symbol	Min	Max	Unit
1	CLKOUT High to TPU Output Channel Valid ^{3, 4}	t_{CHTOV}	2	23	ns
2	CLKOUT High to TPU Output Channel Hold	t_{CHTOH}	0	20	ns
3	TPU Input Channel Pulse Width	t_{TIPW}	4	—	t_{cyc}

NOTES:

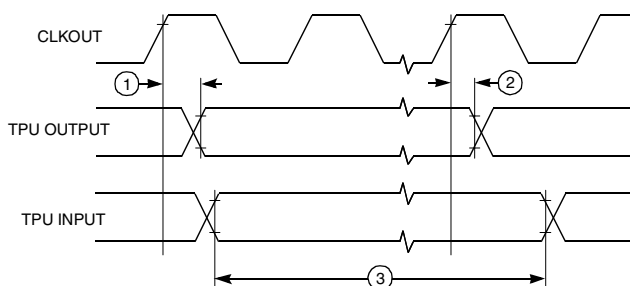
1. Refer to notes in [Table A-31](#).

Table A-31 TPU Timing $(V_{DD} \text{ and } V_{DDSYN} = 5.0 \text{ Vdc} \pm 5\%, V_{SS} = 0 \text{ Vdc}, T_A = T_L \text{ to } T_H, f_{sys} = 16.78 \text{ MHz})^{1, 2}$

Num	Rating	Symbol	Min	Max	Unit
1	CLKOUT High to TPU Output Channel Valid ^{3, 4}	t_{CHTOV}	2	18	ns
2	CLKOUT High to TPU Output Channel Hold	t_{CHTOH}	0	15	ns
3	TPU Input Channel Pulse Width	t_{TIPW}	4	—	t_{cyc}

NOTES:

1. All AC timing is shown with respect to V_{IH}/V_{IL} levels unless otherwise noted.
2. Timing not valid for external T2CLK input.
3. Maximum load capacitance for CLKOUT pin is 90 pF.
4. Maximum load capacitance for TPU output pins is 100 pF.



TPU I/O TIM

Figure A-20 TPU Timing Diagram

